

Essential Features of LARP Strands and Prospects for Still Better High-Field Superconductors

Lance Cooley

Condensed Matter Physics and Materials
Science Department



Outline

- Factors that limit performance of superconductors
- Nb₃Sn: Why has RRP* emerged over bronze-route, MJR†, and PIT‡ as the LARP strand process?
 - Maximizing current density
 - Overcoming limitations imposed by gradients of the tin content
 - Managing stability
- Is further improvement of Nb₃Sn possible?
- If not, what's next? Clues from emerging areas in superconducting materials for HEP

* Restacked Rod Process™

† Modified jelly-roll process

‡ Powder-in-tube process

Our portfolio of long-length superconductors

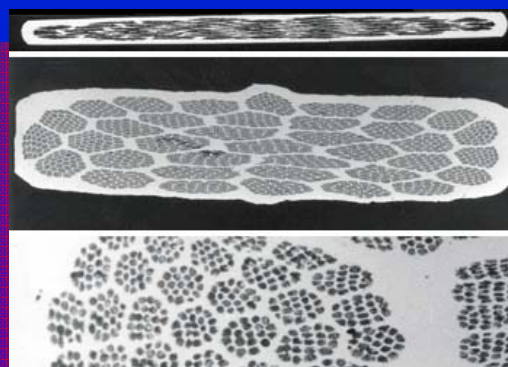
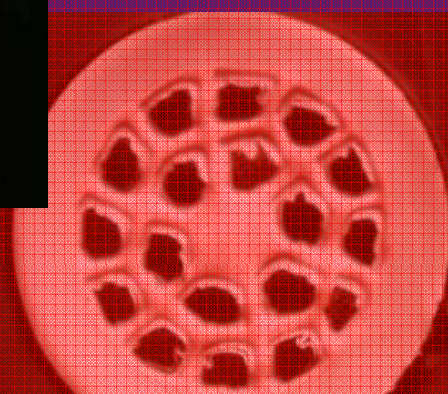
Nb-Ti: \$150/kg, 60¢/m,
\$1.50/kA-m @8T,2K



Nb₃Sn: \$1,000/kg, \$4/m
\$5.50 / kA-m @ 12T, 4K

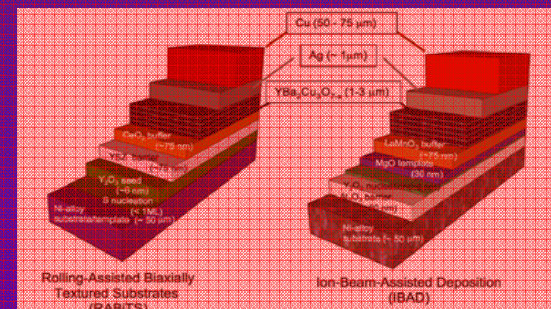


MgB₂: \$50/kg, \$1/m,
\$5/kA-m @2T,20K



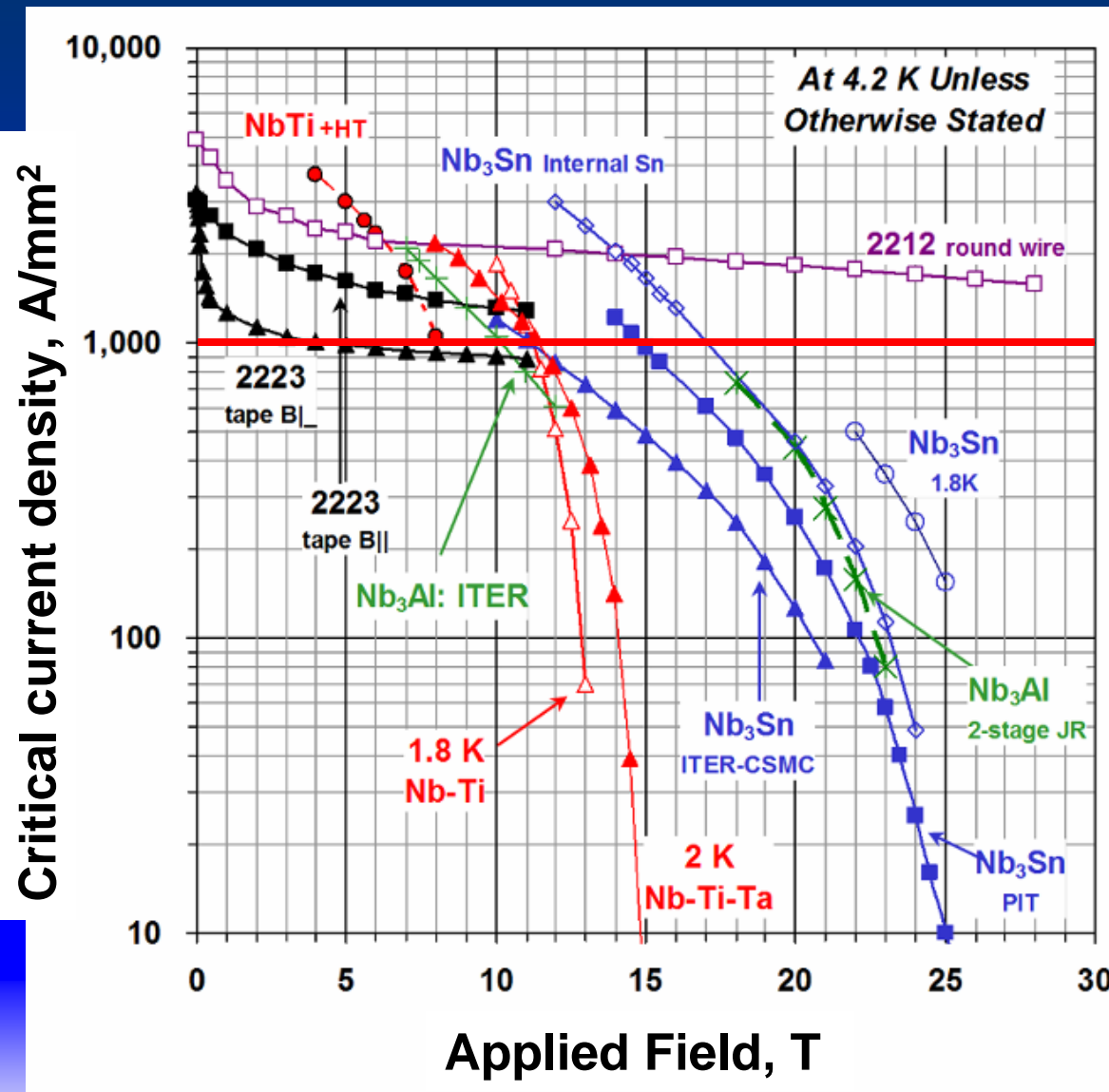
Bi-2212: \$3,000/kg,
>\$10/m, >\$50/kA-m
@20T, 4K

Bi-2223 ("1G")



YBCO ("2G"): >\$100/m,
>\$400/kA-m @ 20T, 4K

Long-length Superconductor Performance



- $J_c, J_c, J_c \dots$
- Plot shows J_c over wire area that is not stabilizer or support
- Highest non-copper area fractions:
 - Nb-Ti ~65%
 - Nb₃Sn ~55%*
 - Bi-2212 ~35%
 - Bi-2223 ~35%
 - MgB₂ ~35%
 - YBCO ~1%
- * Includes Sn and Cu used to convert Nb to Nb₃Sn. Nb₃Sn itself is ~35% of wire area

Plot by Peter Lee <http://magnet.fsu.edu/~lee/>

Performance has limits at multiple levels

- $>100,000 \text{ A/mm}^2$: Depairing current limit (T_c and λ_L)

Cumulative losses that limit current density in practical forms

- Material & physics factors
 - Flux pinning at high fields: 90 to $>99\%$ lost
 - Material anisotropy: large losses in \perp applied fields and at high T
- Factors related to forming the superconductor
 - Diffusion barriers: 2 to 10%
 - Materials needed to form the superconducting phase: 0 to $>90\%$
 - Obstacles and grain connections: 0 to $>90\%$
- Engineering factors
 - Strain, mechanical degradation: 0 to 20% lost
 - Stabilization, mechanical support: 30 to 60% lost

Example: Effects of cumulative limitations on LHC magnet strands

Nb-Ti LHC strand

- $J_D \approx 150,000 \text{ A/mm}^2$
- Flux pinning: 97% lost @ 8T, 2K
- Diffusion barrier: 4% lost
- Copper: 50% lost
- Manufacturing: 25% lost
- Total current density in strand:
 $150,000 \times 0.03 \times 0.96 \times 0.5 \times 0.75 \approx 1,600 \text{ A/mm}^2$

Nb₃Sn LARP strand

- $J_D \approx 400,000 \text{ A/mm}^2$
- Flux pinning: 98% lost 12T, 4.2K
- Nb-Sn reaction: 30% lost
- Diffusion barrier: 10%
- Bronze (or copper + tin) & manufacturing: 40%
- Copper: 50%
- Total current density in strand:
 $400,000 \times 0.02 \times 0.7 \times 0.9 \times 0.6 \times 0.5 \approx 1,500 \text{ A/mm}^2$

Lessons from these analyses

1. The superconductor area must be maximized.
 - The superconductor often is formed during a later reaction.
2. Manufacturing losses should be minimized.
 - Must make long continuous pieces.
 - Must also control shape distortions and other geometric factors.
 - Pure metals have the most ductility!
 - Except for Nb-Ti, high-field superconductors are brittle.
3. All processing must serve the optimization of flux pinning.
 - a. The superconducting properties must be as good as possible.
 - b. The defect nanostructure must be preserved.

Note: (a) and (b) often produce conflicting processing requirements!

Outline

- Factors that limit performance of superconductors
- Nb_3Sn : Why has RRP* has emerged over bronze-route, MJR†, and PIT‡ as the LARP strand process?
 - Maximizing current density
 - Overcoming limitations imposed by gradients of the tin content
 - Managing stability
- Is further improvement of Nb_3Sn possible?
- If not, what's next? Clues from emerging areas in superconducting materials for HEP

* Restacked Rod Process™

† Modified jelly-roll process

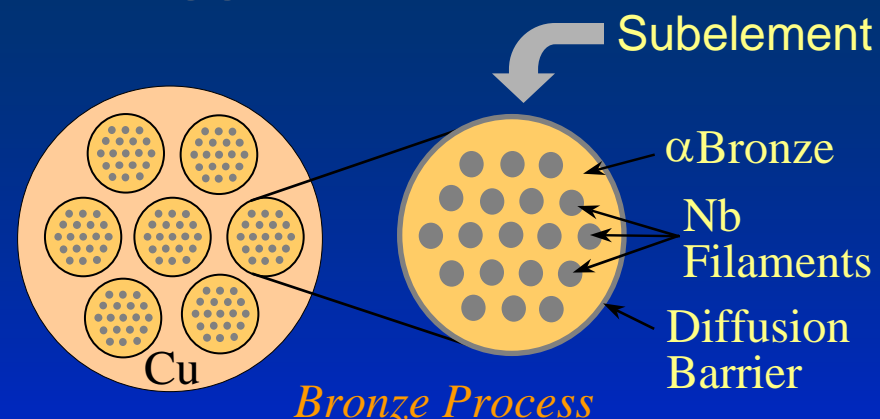
‡ Powder-in-tube process

Solid State Routes to Nb-Sn Wires

Schematic by Mike Naus

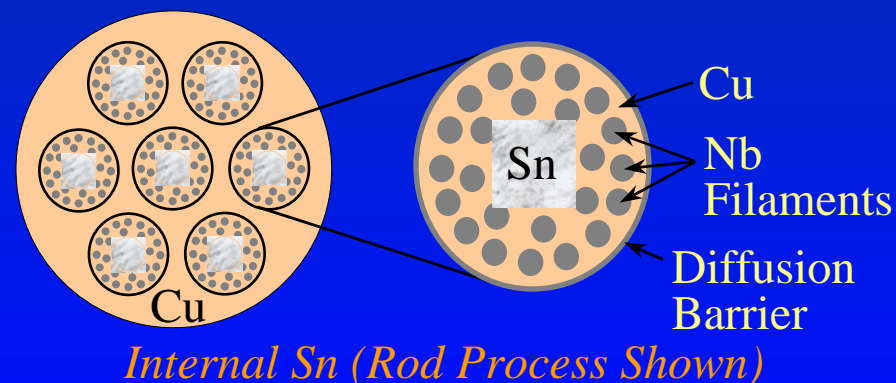
- Bronze route

- Alpha bronze is ductile, but must be annealed often
- 1-10 μm Nb filaments possible



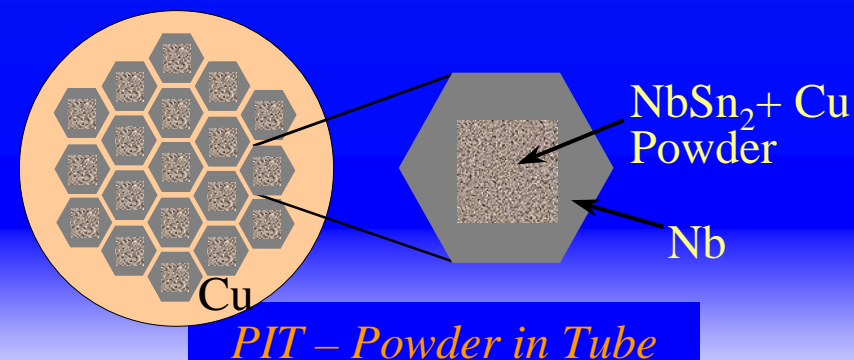
- Internal Sn conductors

- Start from Cu, Sn, Nb alloy
- Components are more ductile than bronze, but pure Sn limits processing temperature



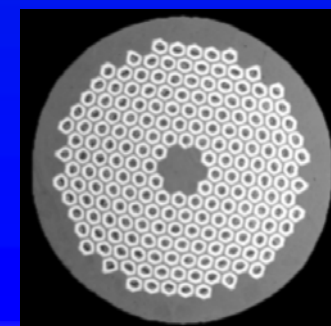
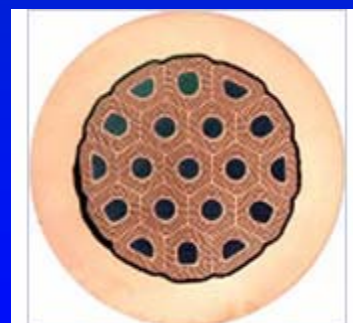
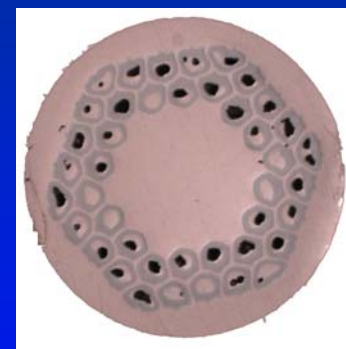
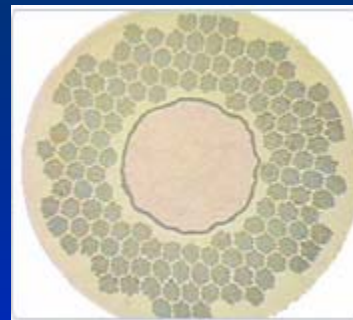
- Powder in Tube (PIT)

- NbSn_2 inside Nb tubes



Nb₃Sn state of the art, c.1998 VLHC workshop

- Bronze-route: $\sim 1,000$ A/mm² available in long length at $> \$15$ per kA-m
- Modified Jelly-Roll (MJR) internal-tin composite: $> 1,500$ A/mm² available in long length at $\sim \$10$ / kA-m
- ITER-style internal tin composite modified for $> 1,500$ A/mm²
- New player: Powder-in-tube



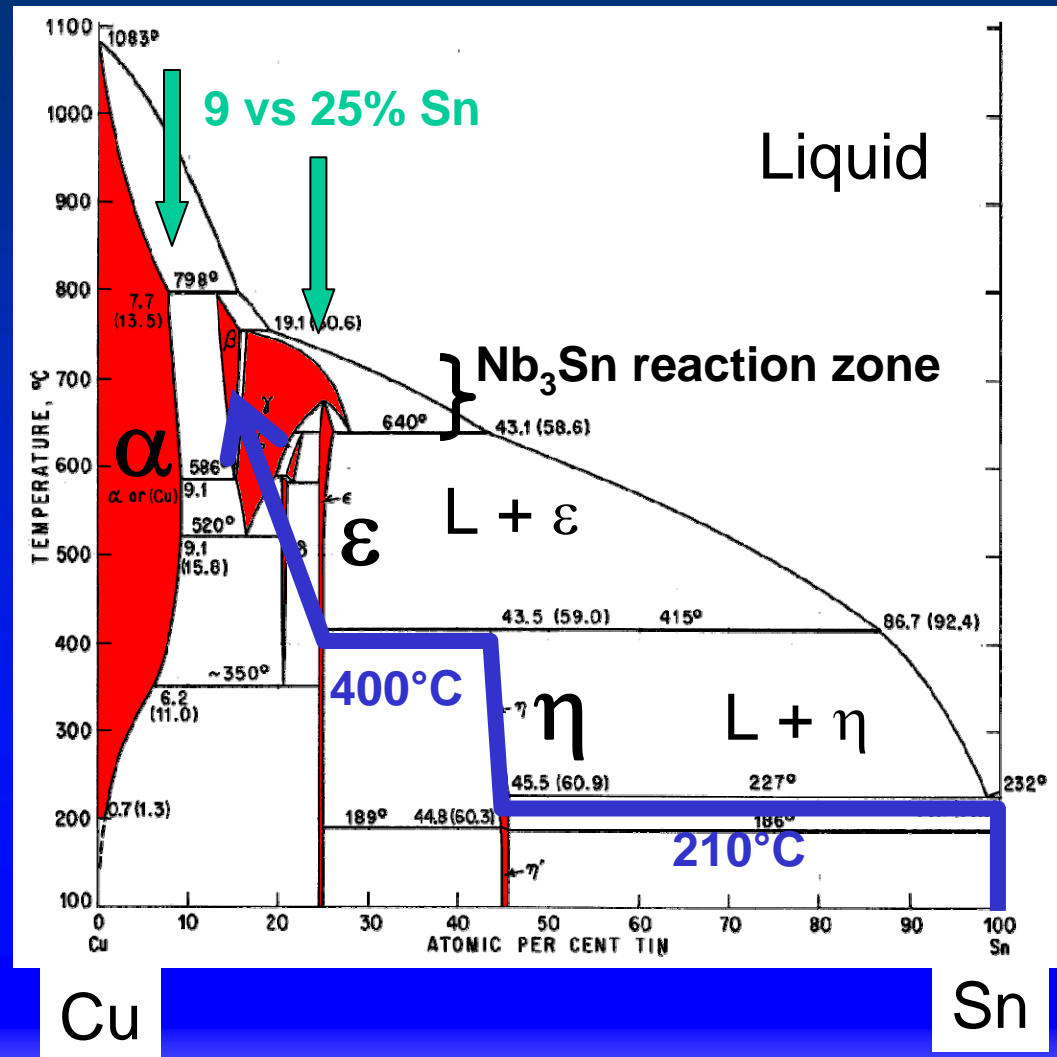
Photos courtesy of Jeff Parrell and Chad Fischer

HEP specifications for VLHC (and LARP) strand

- Nb_3Sn
- $J_c = 3,000 \text{ A/mm}^2$ (non-Cu) @ 12 T, 4.2 K
- Total HT time < 200 hrs
- Effective filament diameter (d_{eff}) < 40 μm
- Average piece length > 10 km at 0.3 to 1.0 mm diameter
- Cost less than \$1.50 / kA-m @ 12 T, 4.2 K

Consequences of Cu-Sn Phase Diagram

- Internal tin routes provide more tin than bronze route
 - Improved tin activity
 - Faster reactions
 - Less wire area required to supply tin atoms
- Reaction strategy avoids melting



Initial response fell short ...

- Subelement redesigned: less Cu, more Nb
- More tin added
- Filaments allowed to merge (so $d_{\text{eff}} = d_{\text{sub}}$)
- Diffusion barrier reacted about halfway through
- Result: 2,000 to 2,200 A/mm², slightly higher cost (but same \$/kA-m)
- Redesign needed \Rightarrow RRP

The Modified Jelly Roll Process

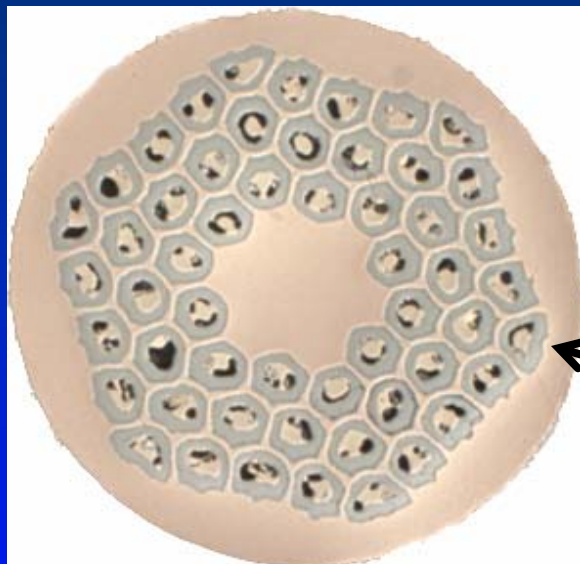
- A. Copper shield.
Expanded niobium mesh.
Solid tin core rod.
- B. Jelly roll formed above is inserted in outer copper tube. Billet is formed ready for drawing.
- C. Billet has been drawn to less than 1/2 inch in diameter.
- D. Rods, approximately 1/2 inch in diameter, are cut to shorter lengths and rebundled in another copper tube.
- E. Up to 50 additional drawing steps reduce material to wire 1/25 inch to 1/100 inch in diameter.

Nb diffusion barrier.



Original niobium expanded mesh becomes extremely long filaments in the finished wire. A single diamond shaped segment will be reduced from 1/4 to 1/3000 inch in cross section and elongated from one inch to one mile.

The LARP strand: Re-stacked Rod Process RRP™



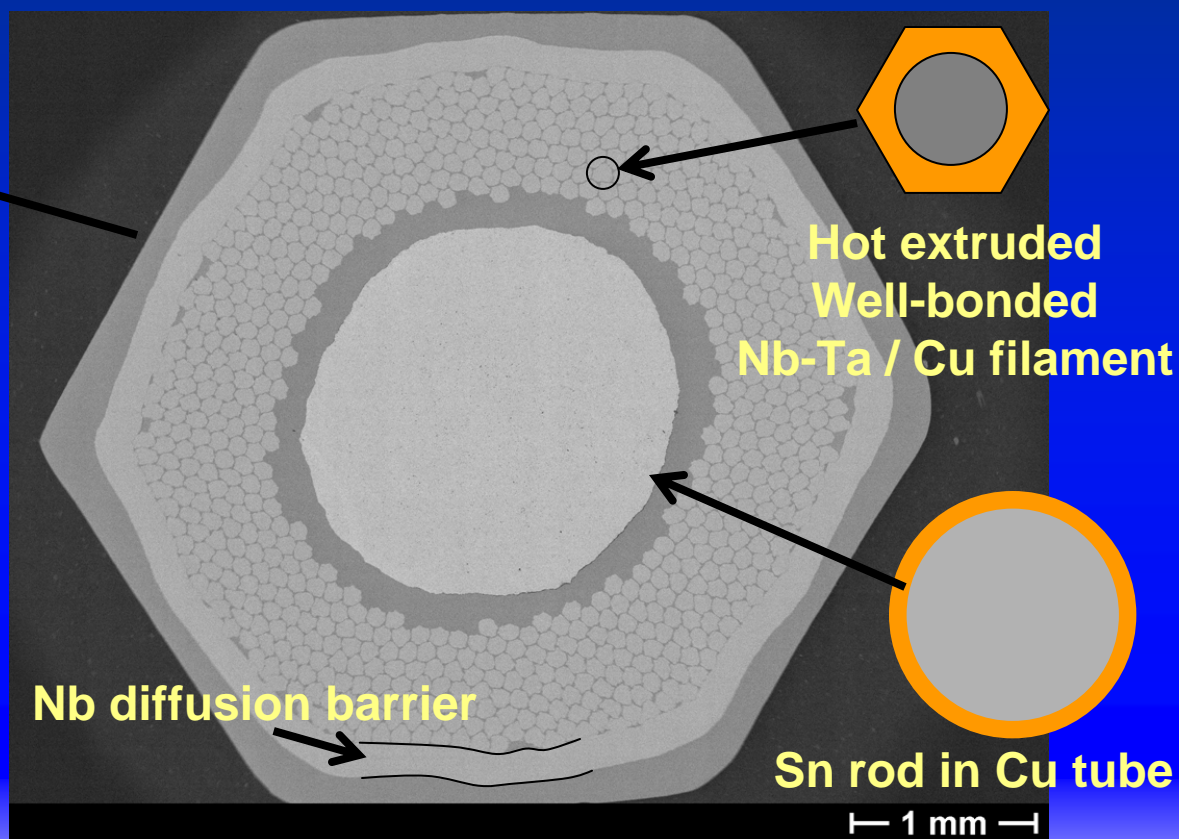
$\text{Nb}_{0.73}\text{Ta}_{0.02}\text{Sn}_{0.25}$
RRP 8220

54 subelements of 61

Cu ~ 48%

$d_s \sim 69 \mu\text{m}$ @ 0.7 mm \varnothing

Subelement combines materials with like surfaces (Cu), results in good bonding and long piece length

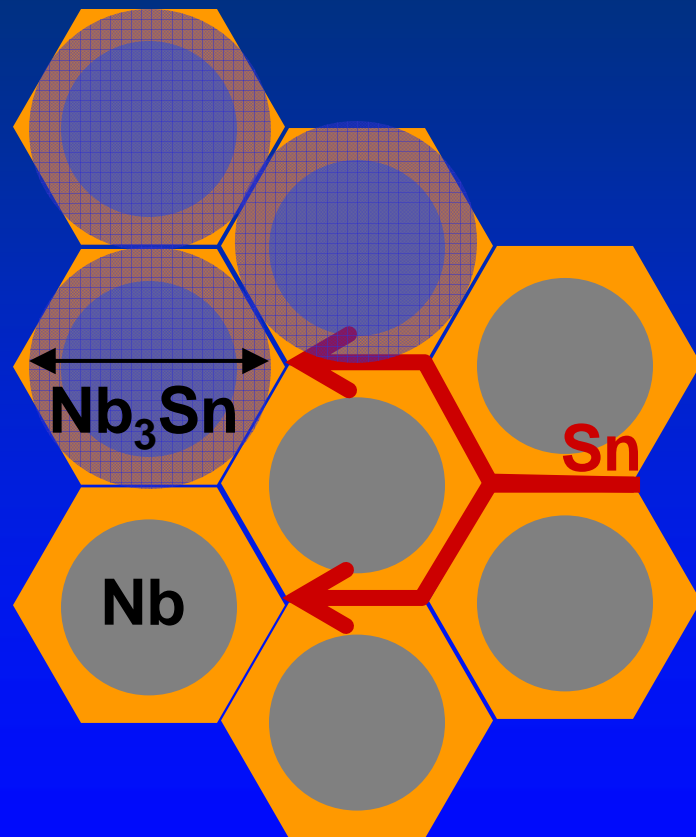


RRP strand gets closer to HEP goals

- Max $J_c \sim 3100 \text{ A/mm}^2$ at 12 T, 4.2 K
- Piece lengths are many kilometers
- Cost \$5.50 / kA-m at 12 T, 4.2 K
- Total reaction time typically 160 hrs
48 h @210°C + 48 h @400°C + 48 h @665°C, with ramp @50°C/h
- Effective filament diameter $d_{\text{eff}} \sim 70 \text{ }\mu\text{m}$ for 54/61 stack
Further progress discussed shortly

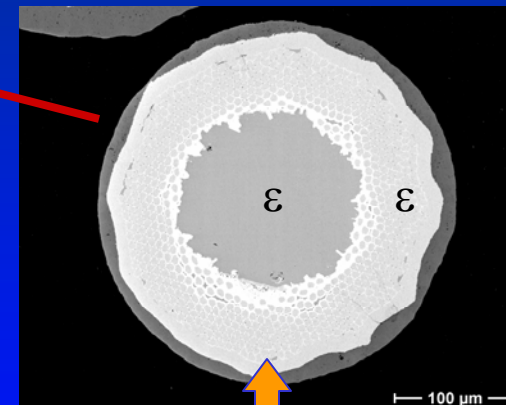
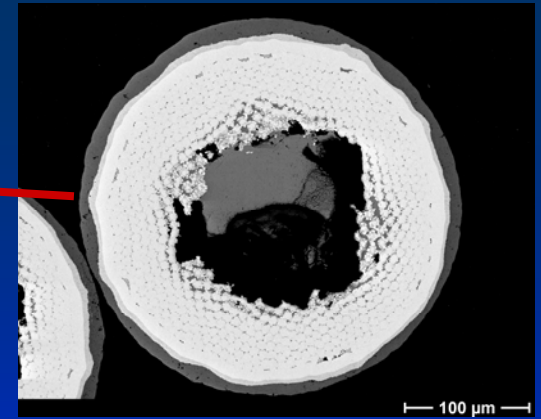
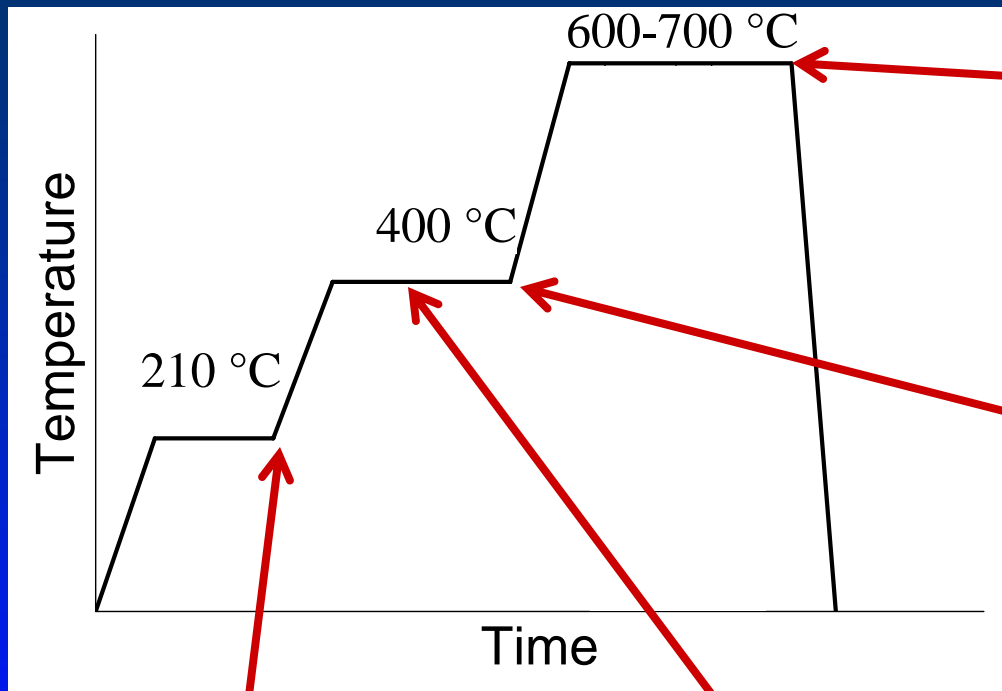
RRP is the engineering strand we need for LARP R&D!!

RRP provides optimum control over Cu:Nb Local Area Ratio (LAR)

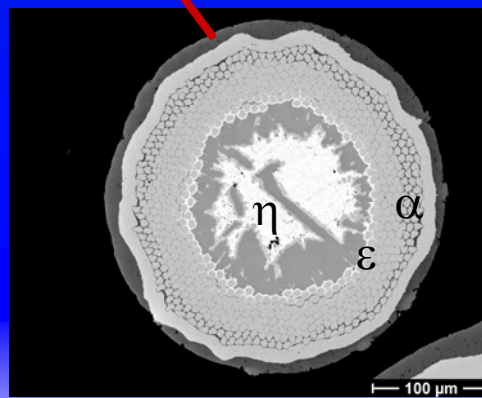
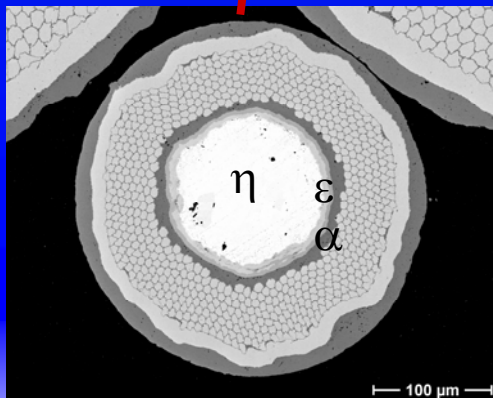


- Lower LAR: more Nb_3Sn is possible if tin can get to Nb
- Higher LAR: wider diffusion pathways for tin
- Shape control reduces pinch-off as filaments grow and gives better balance of opposed trends above
 - Nb increases area by 37% upon conversion to Nb_3Sn

Typical reaction sequence



25% tin bronze (ϵ) is uniformly distributed prior to formation of Nb_3Sn



Microscopy by Seth Hynes, M.S. 2003 Wisconsin

RRP addressed critical current lessons

1. The superconductor area must be maximized.



- The superconductor often is formed during a later reaction.

2. Manufacturing losses should be minimized.



- Must make long continuous pieces.
- Must also control shape distortions and other geometric factors.
- Pure metals have the most ductility!
- Except for Nb-Ti, high-field superconductors are brittle.

3. All processing must serve the optimization of flux pinning.

Next...

Superconducting properties must be as good as possible.
Exact nanostructure must be preserved.

Note: (a) and (b) often produce conflicting processing requirements!

Outline

- Factors that limit performance of superconductors
- Nb_3Sn : Why has RRP* has emerged over bronze-route, MJR†, and PIT‡ as the LARP strand process?
 - Maximizing current density
 - Overcoming limitations imposed by gradients of the tin content
 - Managing stability
- Is further improvement of Nb_3Sn possible?
- If not, what's next? Clues from emerging areas in superconducting materials for HEP

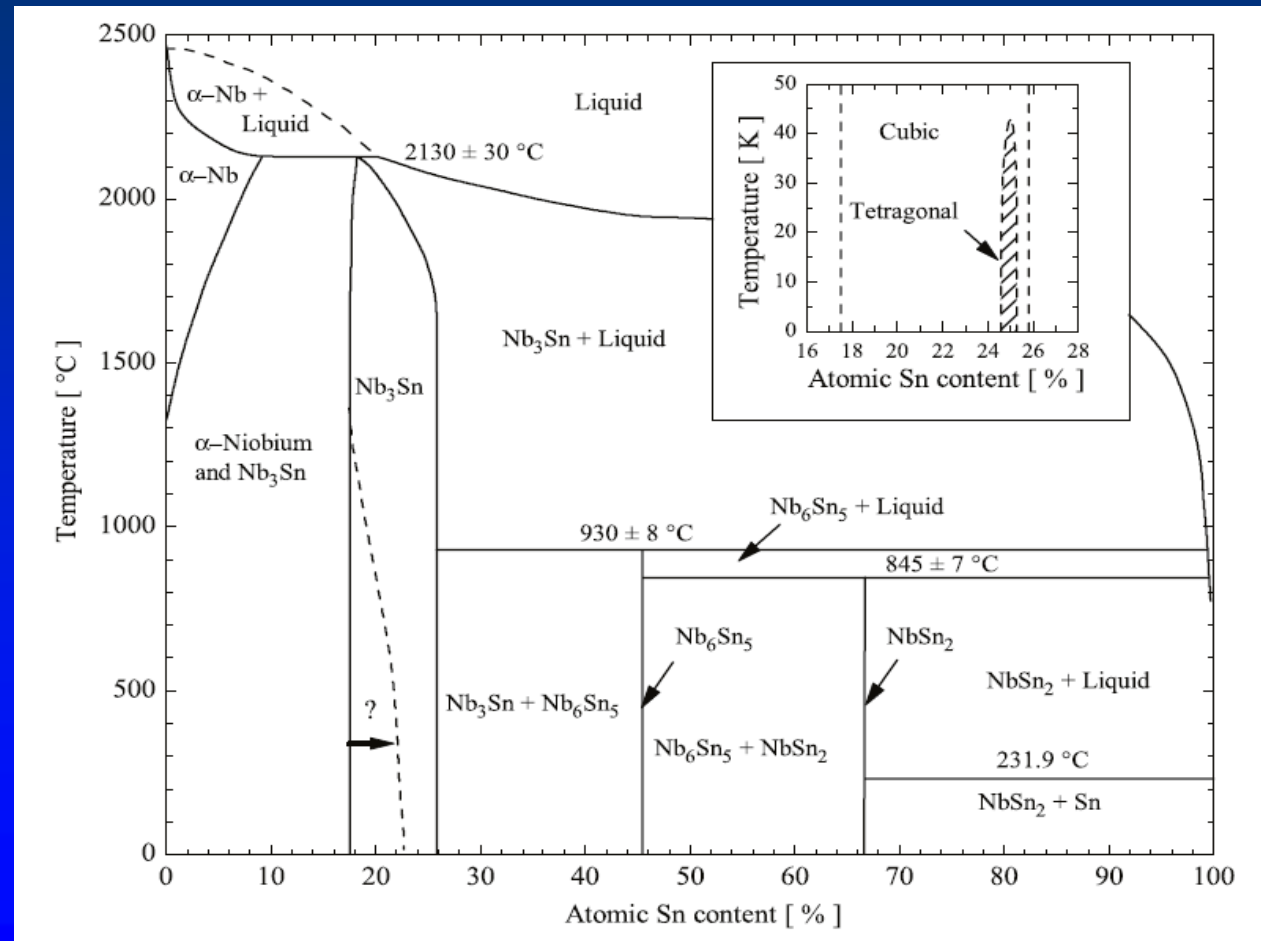
* Restacked Rod Process™

† Modified jelly-roll process

‡ Powder-in-tube process

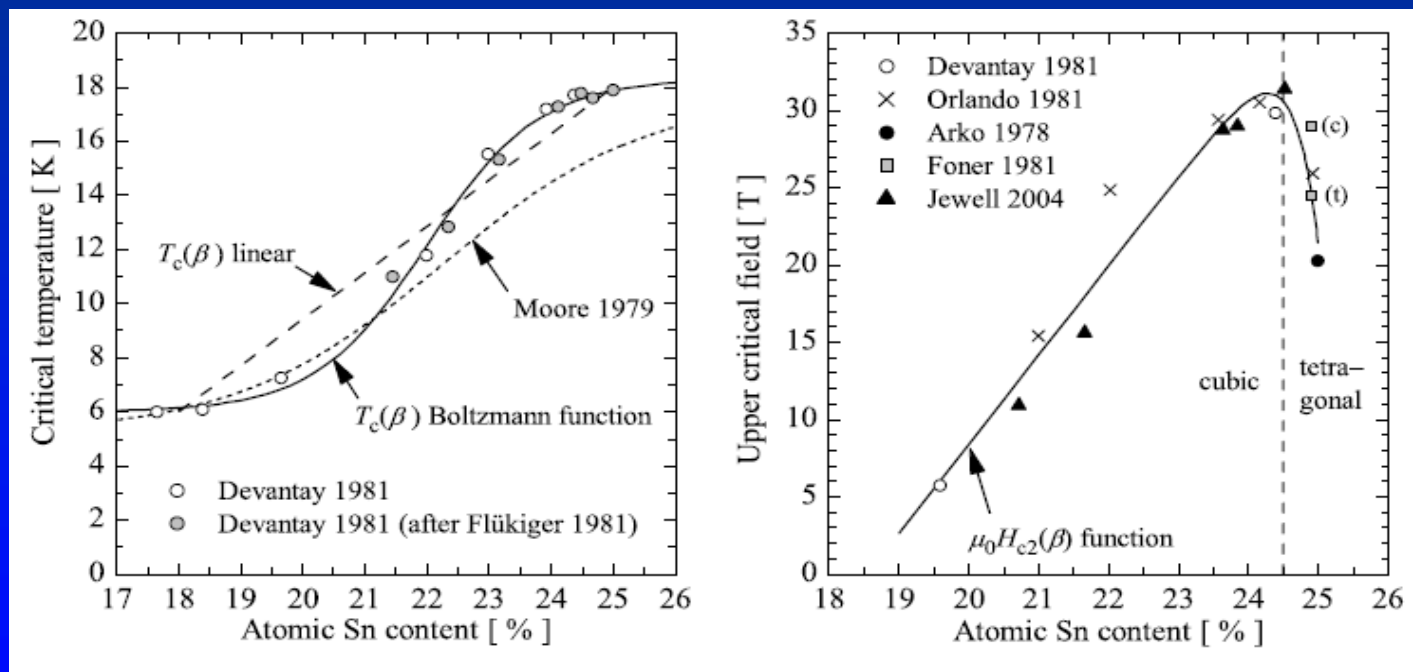
Consequences of Nb-Sn phase diagram

- The desired Nb_3Sn phase exists from 18 to 25.5% Sn
- Thermo: Any solid-state reaction MUST produce a variation of %Sn across the SC layer
- Must have high kinetics: Variations in %Sn then occur steeply across small regions



Composition variation leads to property variation

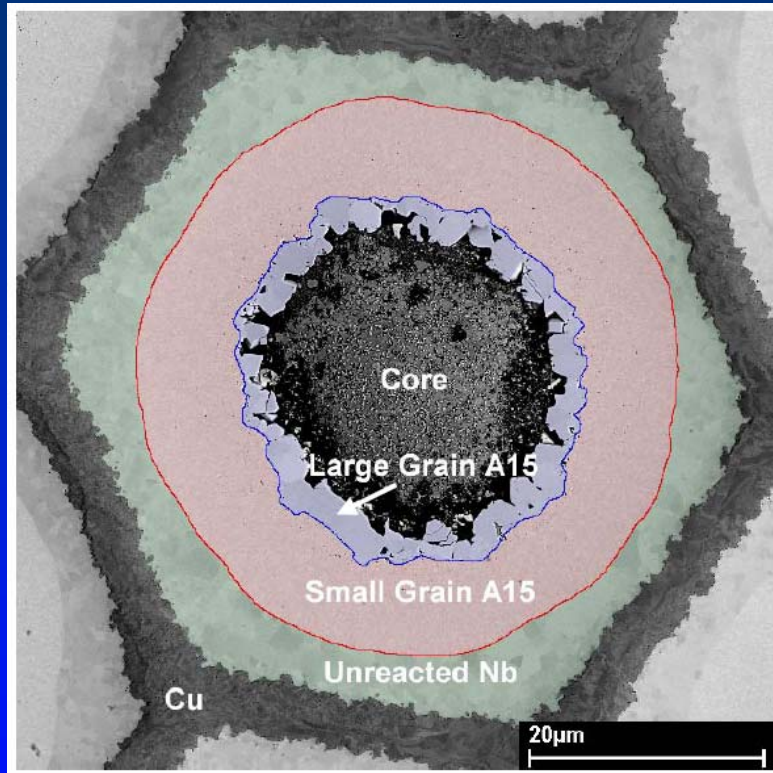
- More tin = better superconductor
- What are the consequences for strands?



Critical Temperature

Upper Critical Field
(unalloyed)

PIT Nb₃Sn wires are a model system to study Sn gradients

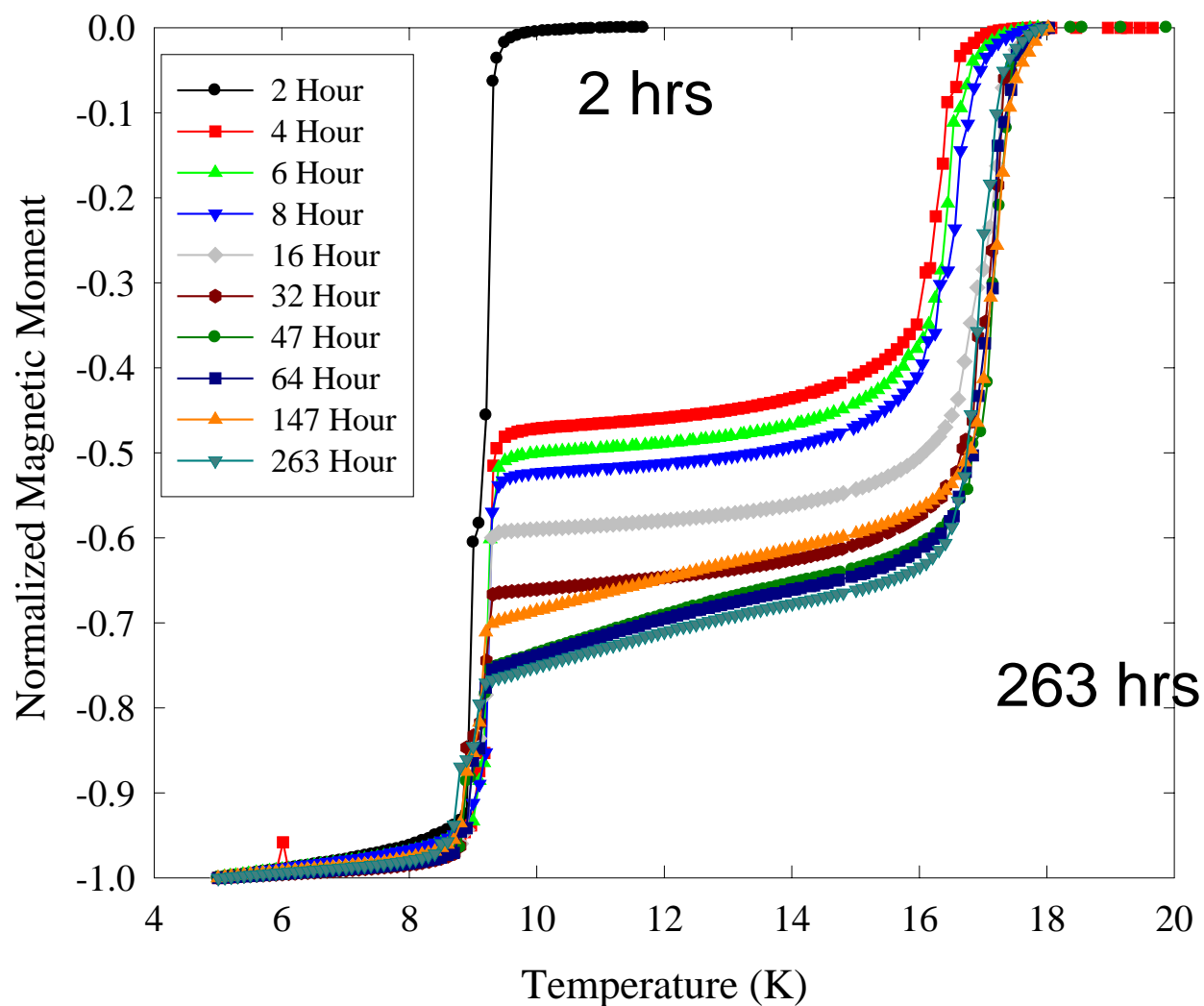


- PIT is RRP in the limit of no copper (LAR = 0)
- Tin diffuses radially outward
- A new morphology forms:
large grains near core
 - Large grains have poor flux pinning and do not contribute to current-carrying area

Lowest %Sn is on outside
⇒ transparent to magnetic probes!

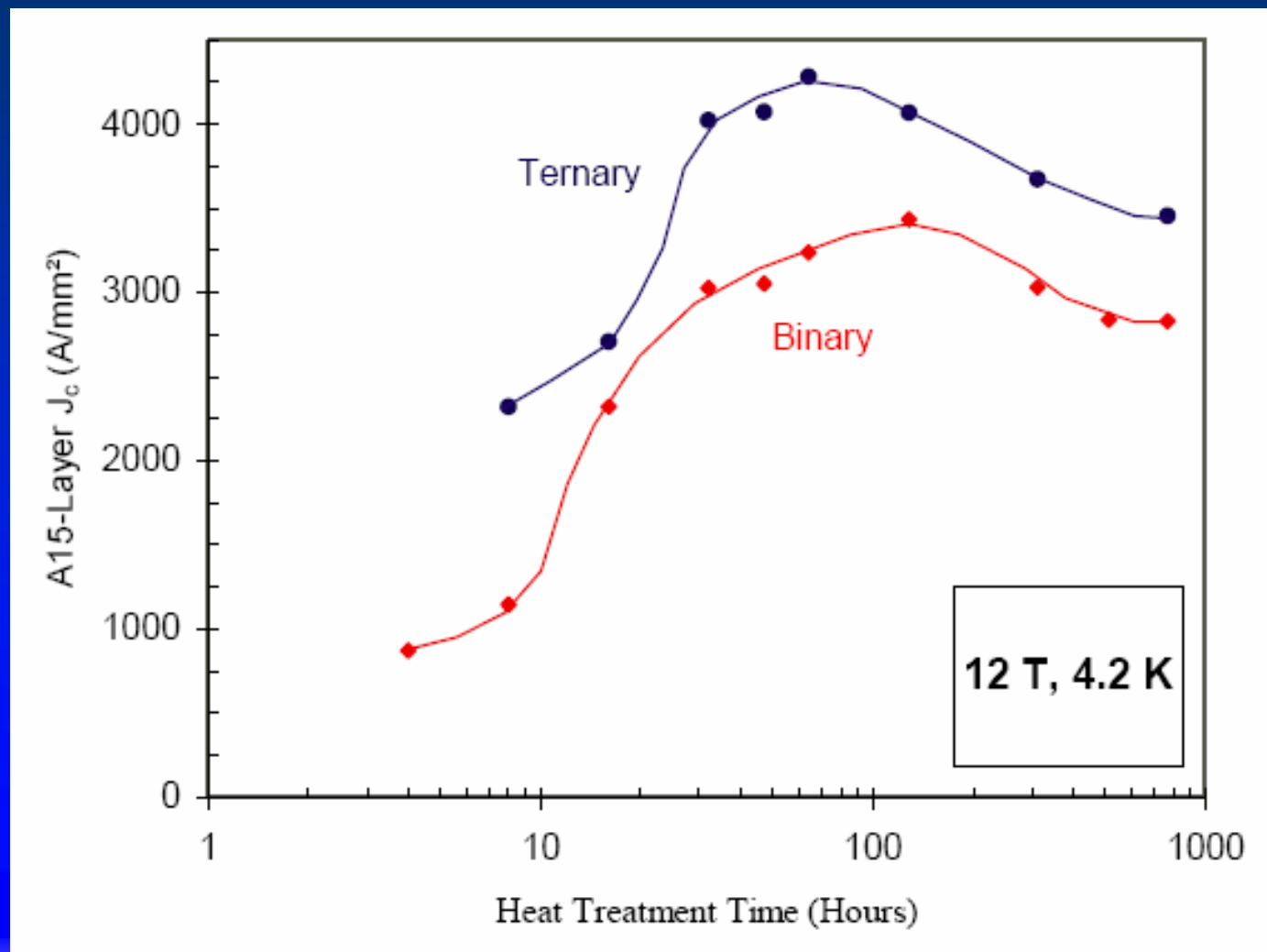
Strands courtesy Jan Lindenhoevis, SMI
Photos courtesy Chad Fischer (M.S. Thesis, Wisconsin 2002)
and Peter Lee (see magnet.fsu.edu/~lee)

Longer time @ 675°C: more Nb₃Sn, higher T_c



Chris Hawes et al, SuST (EUCAS invited) 2006

Longer time @ 675°C: flux pinning peaks, drops



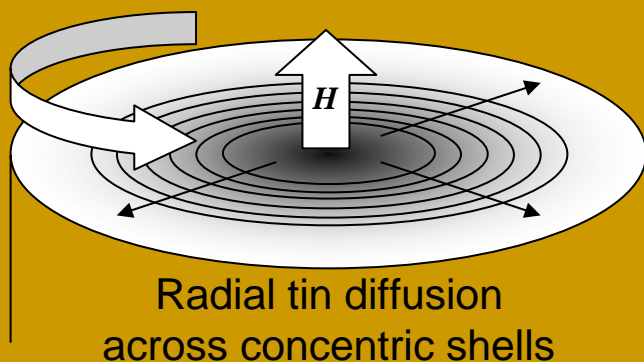
PIT Lesson 1:

Optimization of performance is complex!

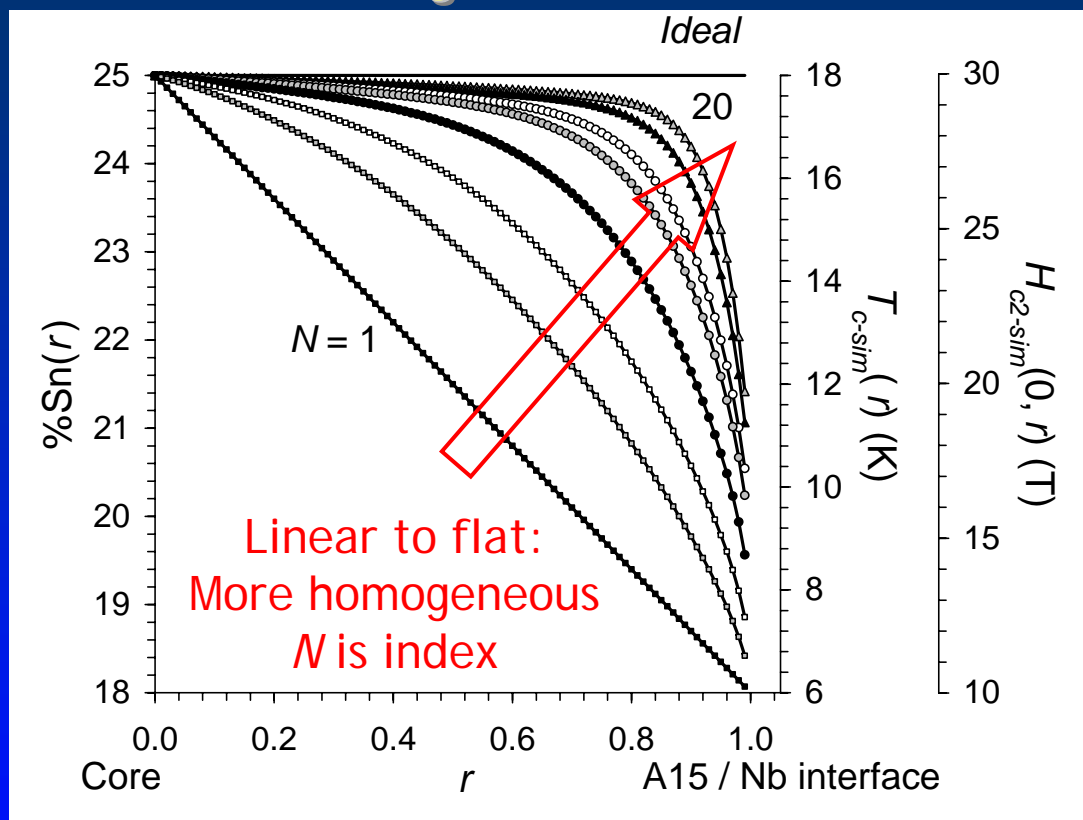
- Longer time @ temperature, or higher temperature at fixed time...
 - ... Produces more superconductor
 - ... Produces higher T_c and B_{c2} , which increase flux pinning
 - ... Eventually produces larger grains, which **reduces** flux pinning and the J_c of the Nb_3Sn layer
- Overall $J_c(T,H) = J_c \text{ layer} \times \text{amount of } Nb_3Sn$
- Mapping of optimum time / temperature matrix can be different for each wire
 - Tight geometry control is needed for reproducible HT recipe

Simulated tin gradients in PIT Nb₃Sn wires

Magnetization current



- Divide %Sn(*r*) profile into 100 points
 - *Concentric shells of magnetization current*
- From %Sn(*r*) get *T_c*(*r*), *H_{c2}*(0,*r*)



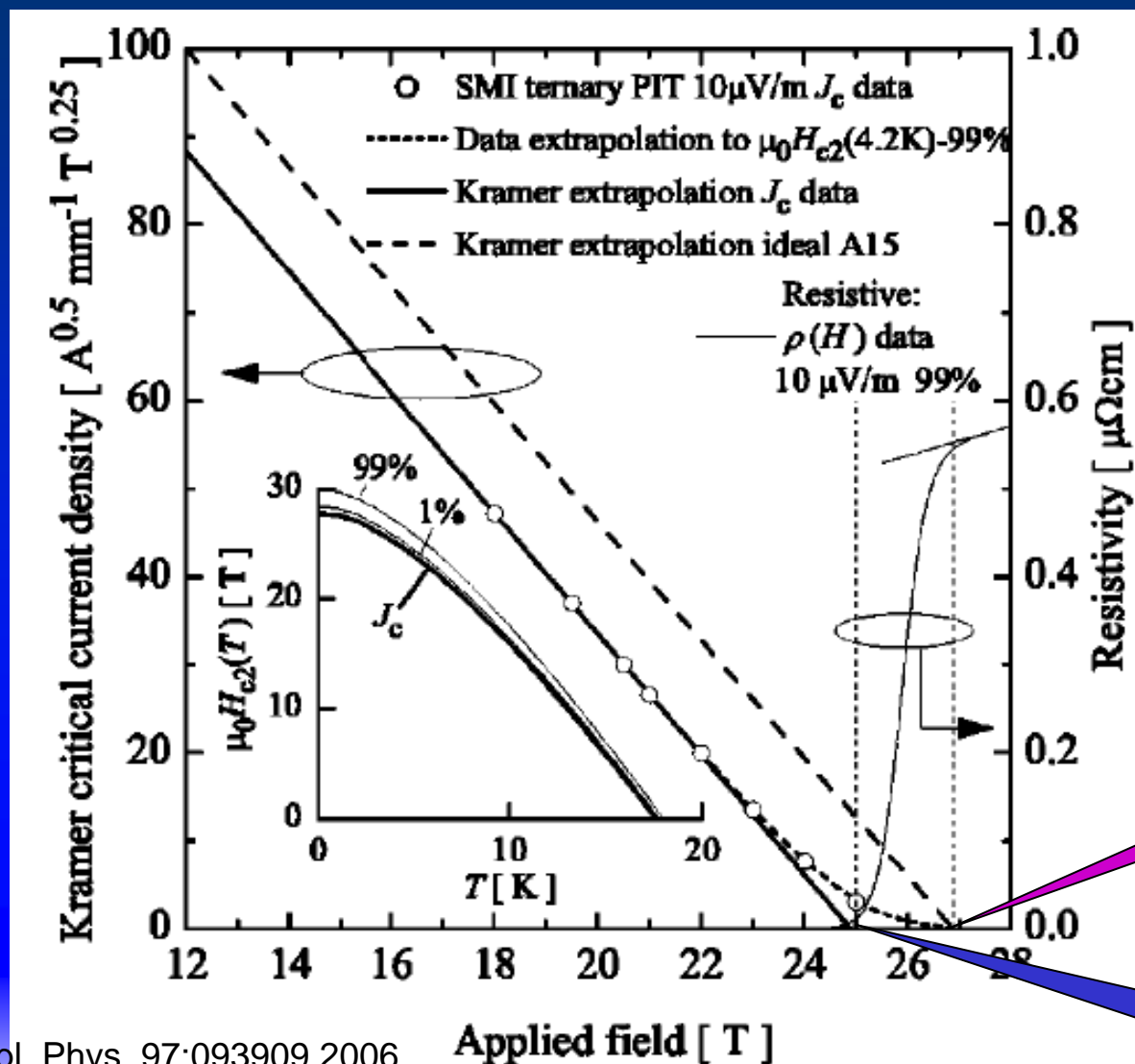
$$\%Sn(r) = 18 + 3.5 [1 - r^N + (1 - r)^N]$$

$$T_{c-sim}(r) = 6 + 12 [(\%Sn(r) - 18) / 7] \text{ Kelvin}$$

$$\mu_0 H_{c2-sim}(0,r) = 0.69 \cdot 2.4 \cdot T_{c-sim}(r) \text{ Tesla}$$

L. D. Cooley, C. M. Fischer, P. J. Lee, and D. C. Larbalestier, J. Appl. Phys. 2004.

Kramer plot extrapolation field $\mu_0 H_K$



Godeke et al., J Appl. Phys. 97:093909 2006

Kramer extrapolation represents average of $H_{c2}(\%Sn)$

Flatter profiles

Gradient index N	Weighted mean of $H_{c2-sim}(r)$ at 4.2 K (T)	H_K at 4.2 K (T)	Weighted mean of $H_{c2-sim}(r)$ at 12 K (T)	H_K at 12 K (T)
1	15.7	19.1	7.1	9.6
5	23.0	23.3	10.5	11.4
10	24.6	24.6	11.7	12.1
Ideal	26.5	26.4	13.6	13.6

This is the average $H_{c2}(\%Sn)$, which is always less than the ideal value (H_{c2} @ 25% Sn).

This is the Kramer plot extrapolation that fixes $J_c(H)$

PIT Lesson 2:

%Sn profile is averaged by critical current

- To improve performance at high fields, it is absolutely necessary to minimize the number of tin-poor regions
- $J_c(H)$ scales with $H_K = \text{average } H_{c2}(\%Sn)$
- RRP advantage over PIT: Cu provides rapid pathways for radial diffusion of Sn, eliminating radial Sn gradients
 - Because Cu in RRP diffuses toward the tin core, practically no tin-poor Nb_3Sn area results. Thus, RRP produces better Nb_3Sn AND does it more efficiently.
 - By contrast, the large-grain region wastes ~20% of the Nb_3Sn layer in PIT, even though it is rich in Sn.

Summary of RRP advantages

- Well bonded materials give long pieces
- Control and flexibility of LAR permits systematic adjustment of tin diffusion
- High tin activity produces rapid reactions and minimizes extent of tin-poor regions
- Radial dispersion of tin prior to formation of Nb_3Sn reduces gradients

Outline

- Factors that limit performance of superconductors
- Nb_3Sn : Why has RRP* emerged over bronze-route, MJR†, and PIT‡ as the LARP strand process?
 - Maximizing current density
 - Overcoming limitations imposed by gradients of the tin content
 - Managing stability
- Is further improvement of Nb_3Sn possible?
- If not, what's next? Clues from emerging areas in superconducting materials for HEP

* Restacked Rod Process™

† Modified jelly-roll process

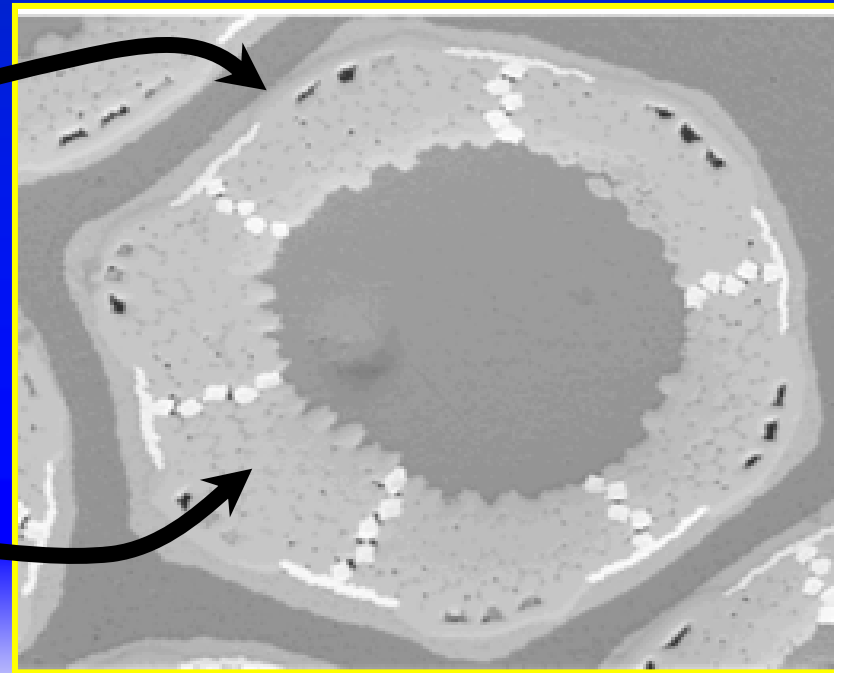
‡ Powder-in-tube process

Origins of strand instability

- Large d_{eff} makes wires prone to flux jumps
- If heat released by flux jump cannot escape to helium in time (e.g. due to dirty copper), strand will quench
- Many magnets can operate with unstable strands!

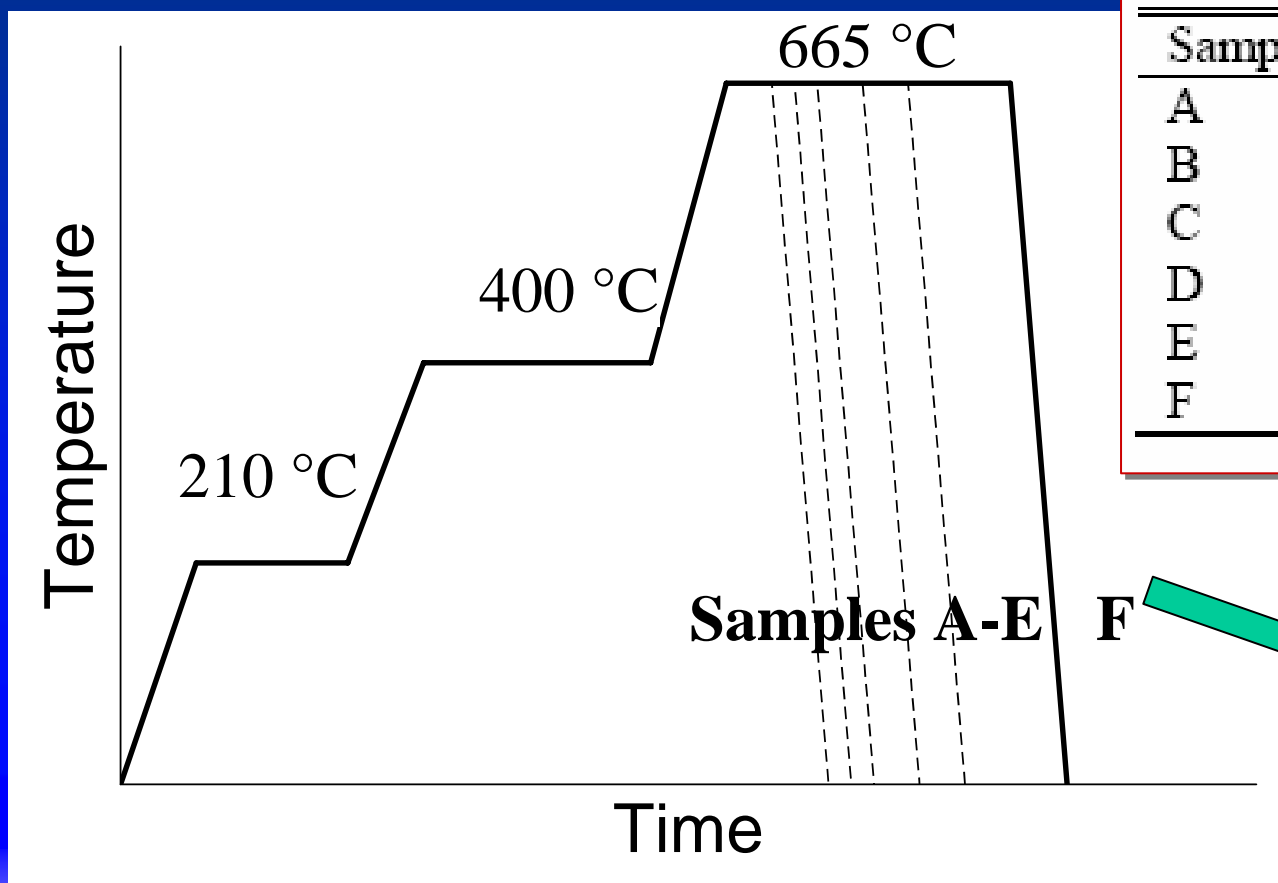
Tin may breach the barrier and contaminate copper

Filaments merge into a solid superconducting mass after reaction
(Sometimes separators are incorporated to break up the filament ring, as shown here)

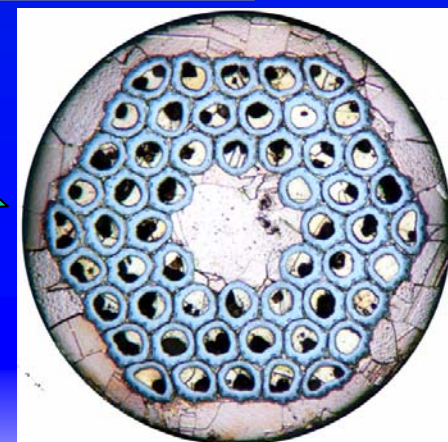
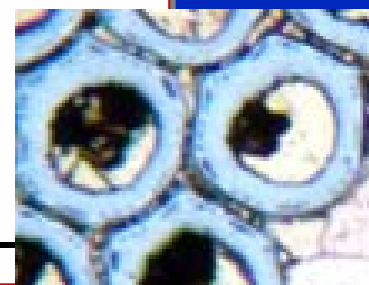


Experiment - RRP 7054 (LARP predecessor)

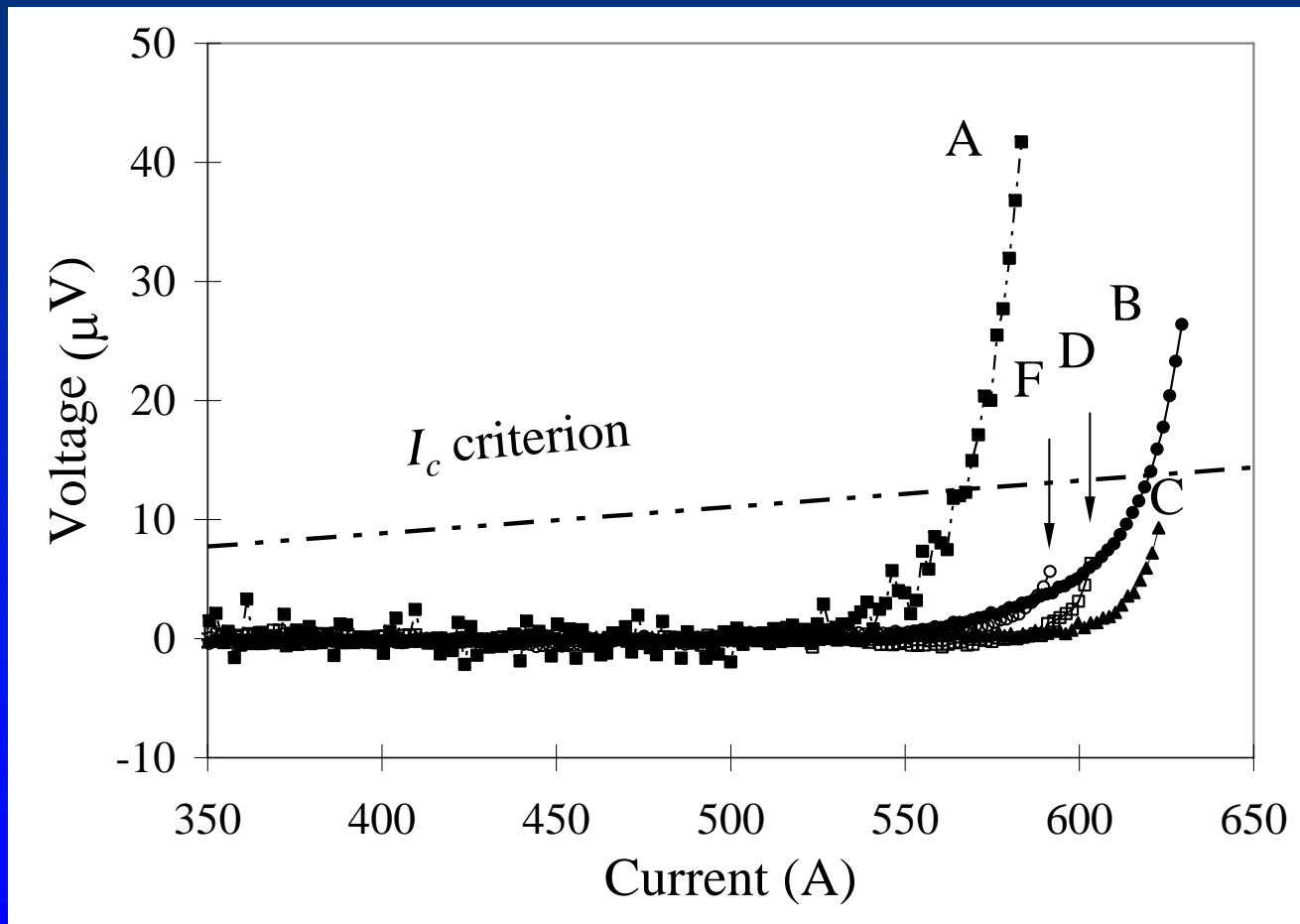
Limit reaction to keep tin from leaking through Nb barrier



Sample	HT time (h)
A	24
B	36
C	48
D	72
E	96
F	150



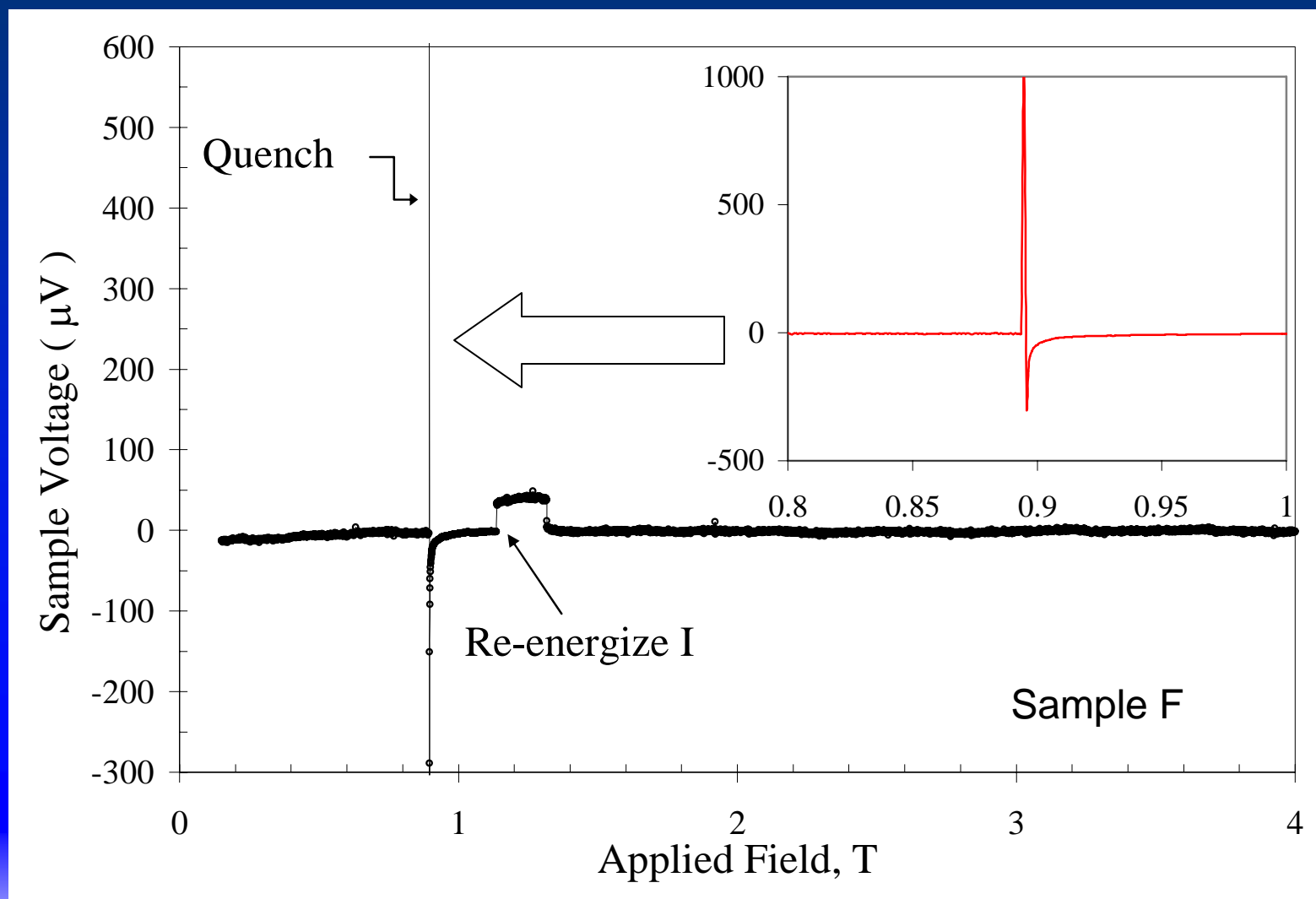
High tin activity helps J_c reach 90% of the maximum J_c for a reaction of only 24 hours



Voltage-current transitions acquired at 11.5 T for samples A-F. The resistivity criterion used to determine I_c is also shown.

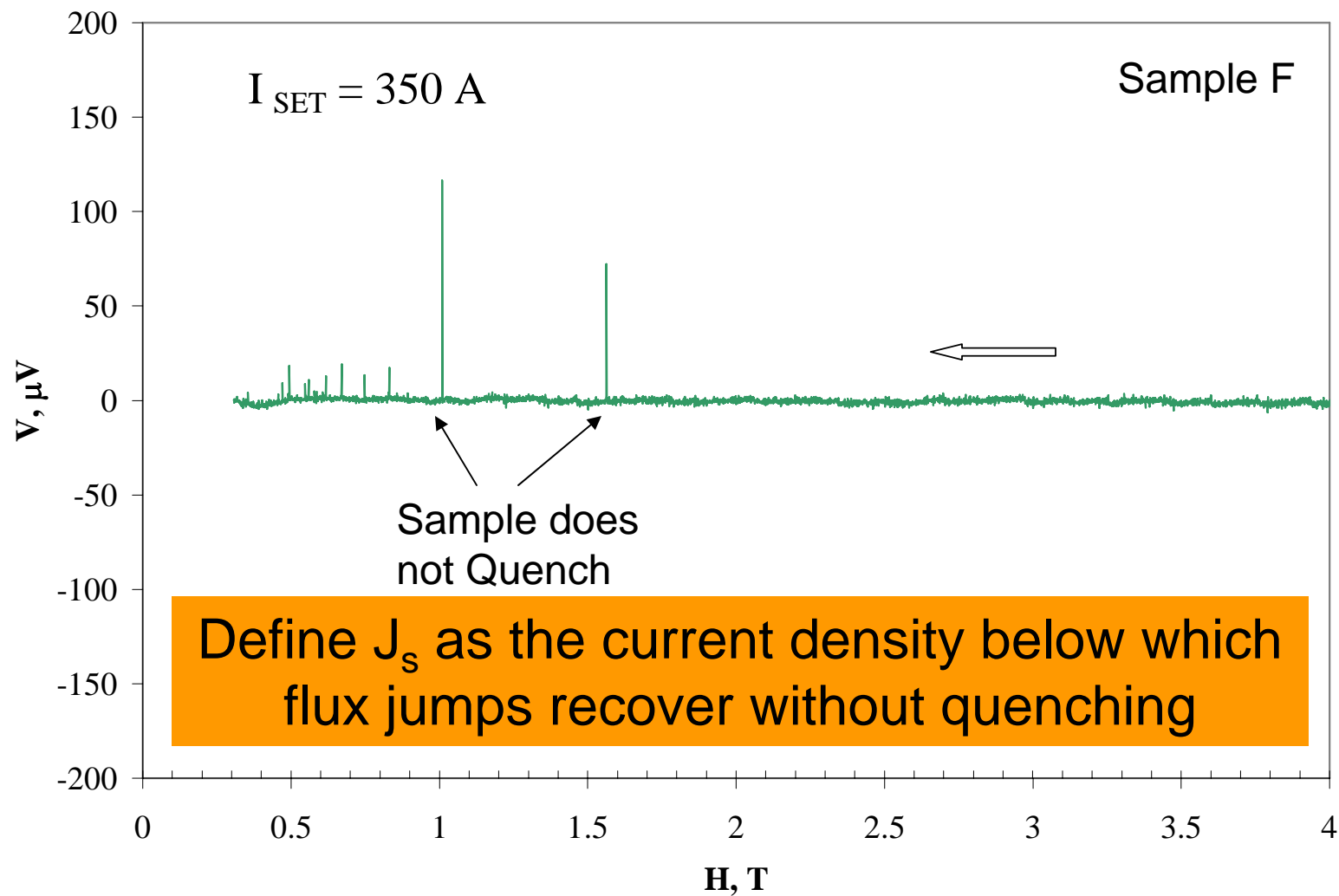
Non-Traditional V-H plot

$I_{\text{SET}} = 400 \text{ A}$ $dB/dt = 5 \text{ mT/s}$



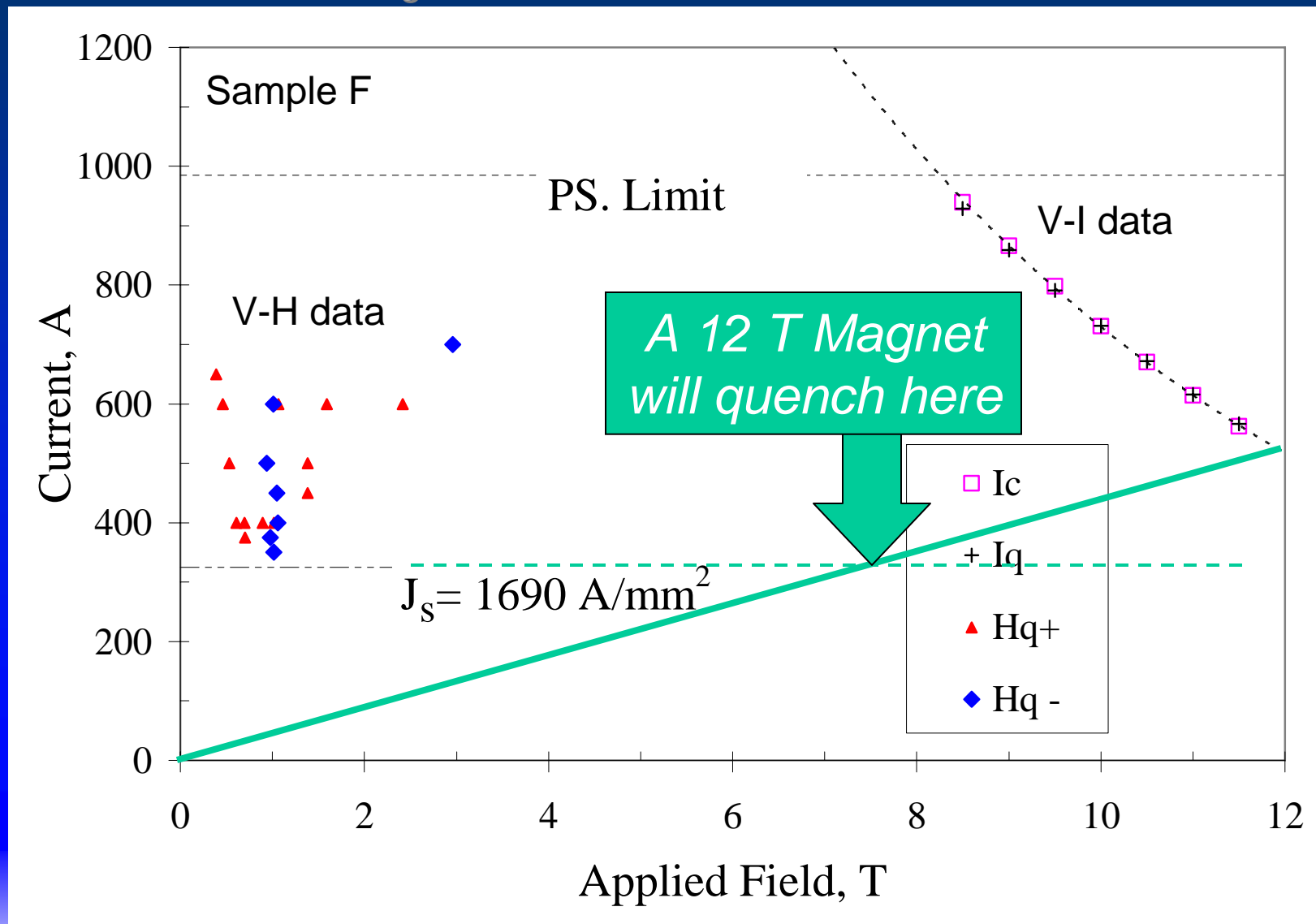
Arup Ghosh, ASC 2004

Dynamic stability threshold

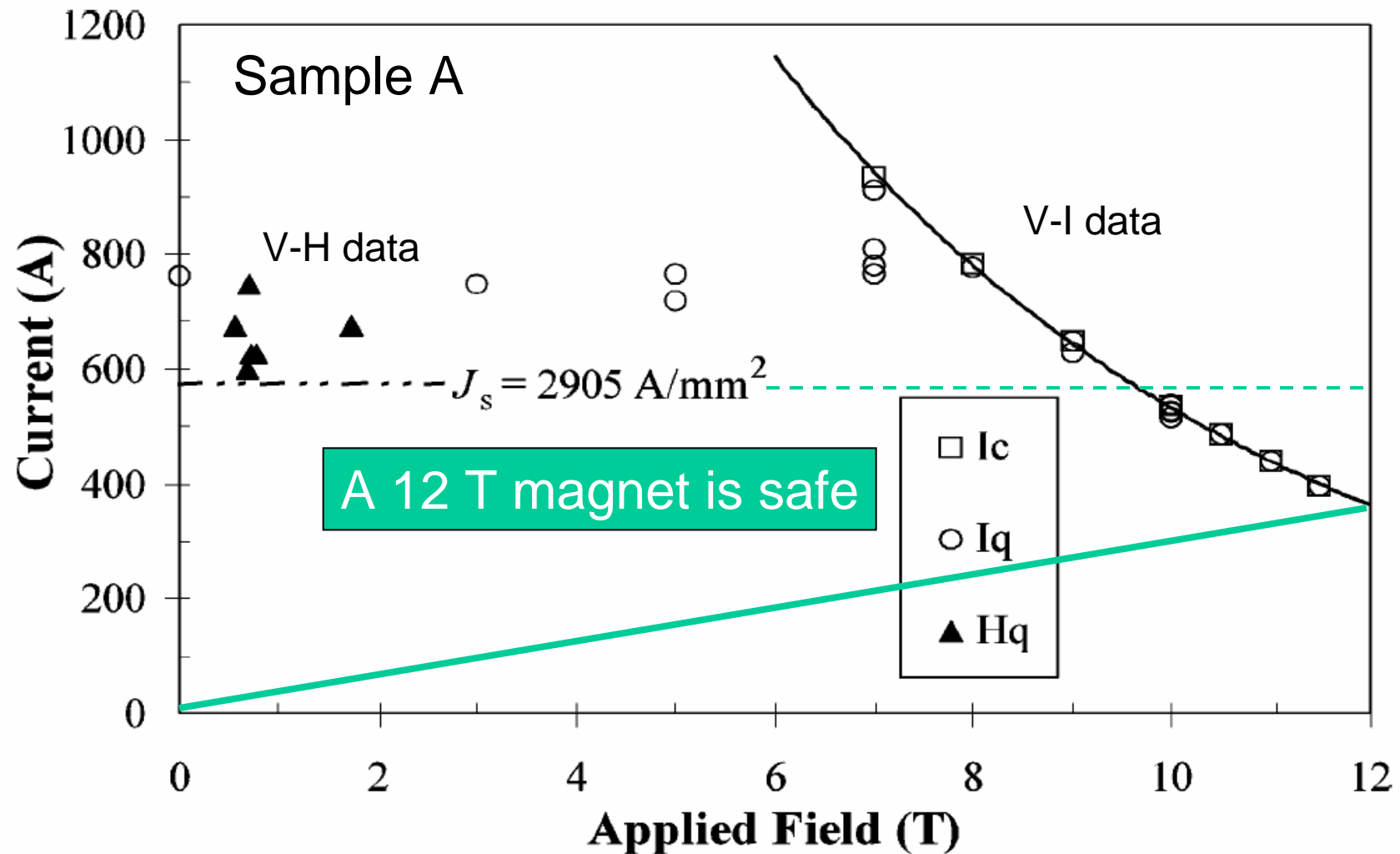


Arup Ghosh, ASC 2004

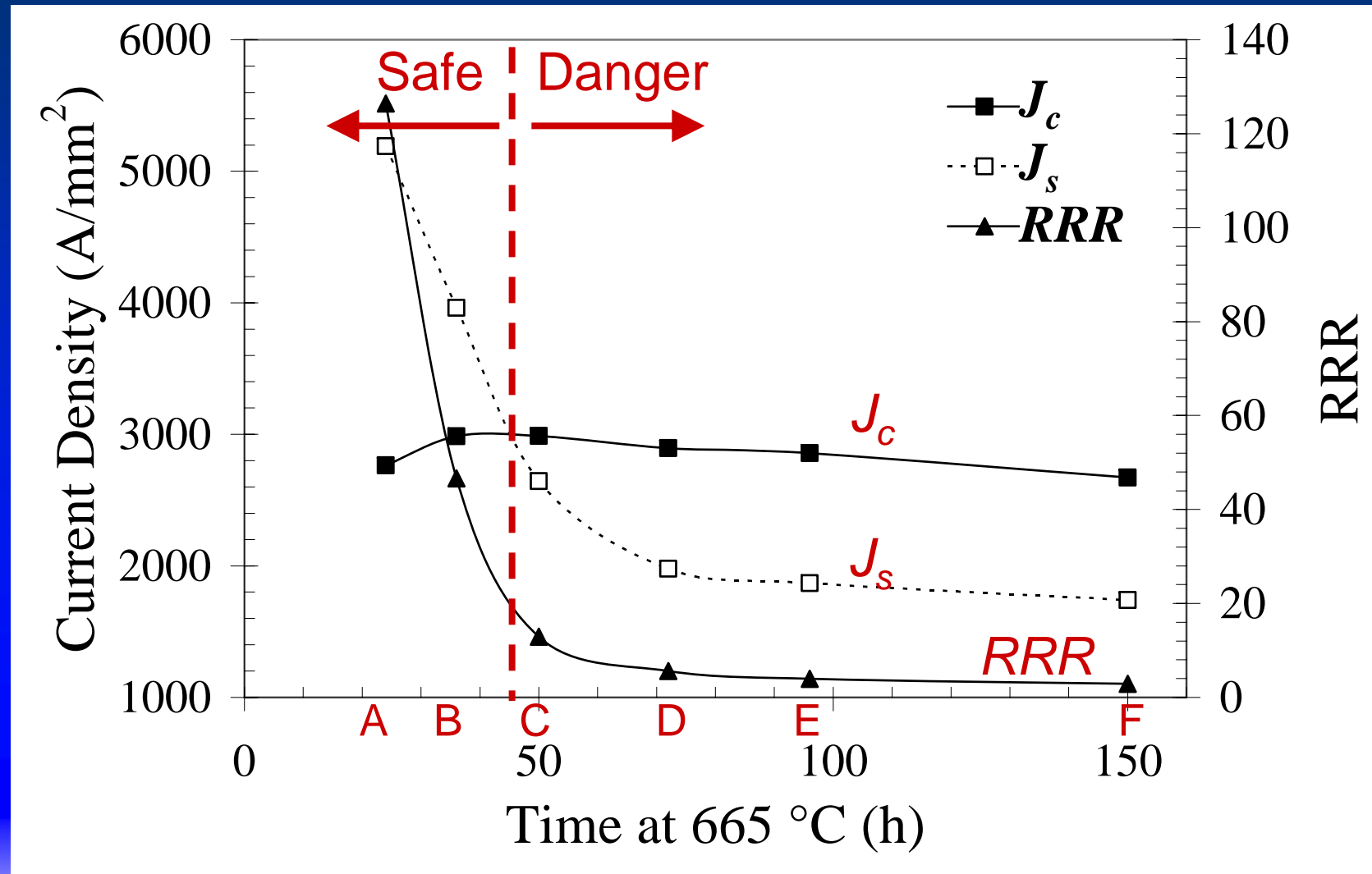
J_s is far below $J_c(12\text{ T})$ when RRR is low



J_s is above $J_c(12\text{ T})$ when RRR is high



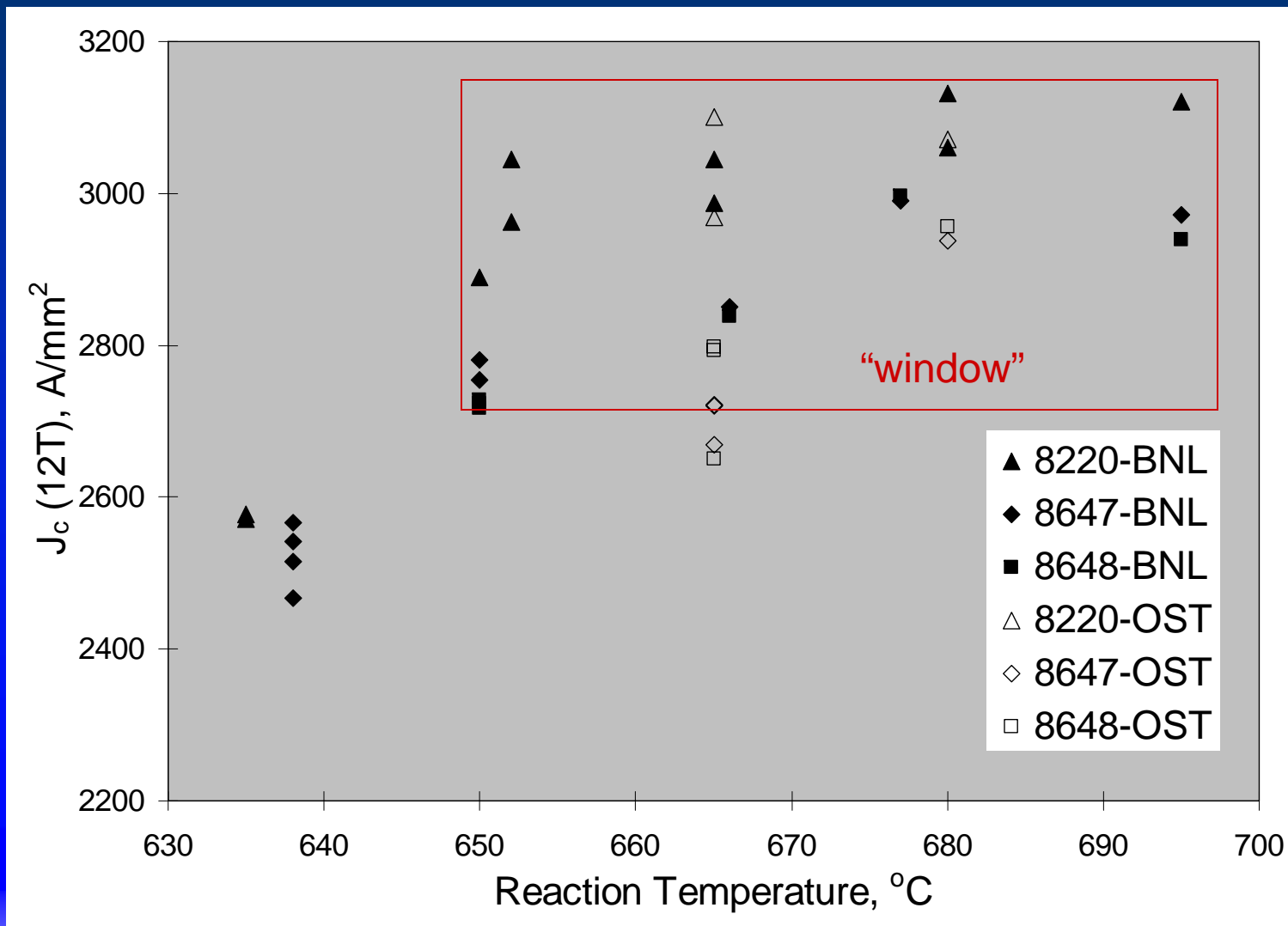
Experiment Summary: Keep $J_s > J_c$



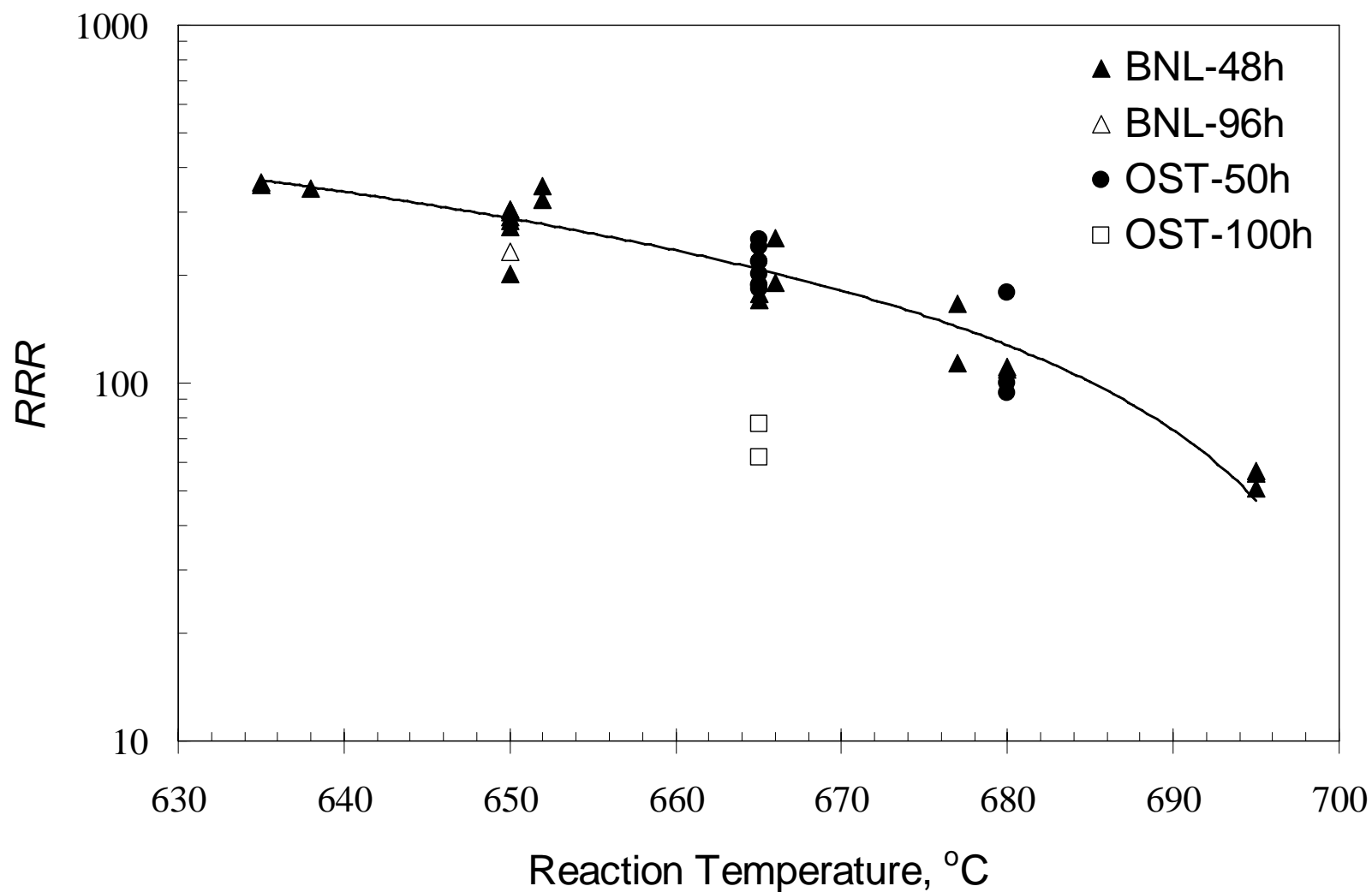
Lessons from stability work

- Two parameters (RRR and J_c) must be optimized.
- Fortunately, RRP provides so much tin activity that J_c optimizes rapidly, opening a fairly wide window to tune RRR

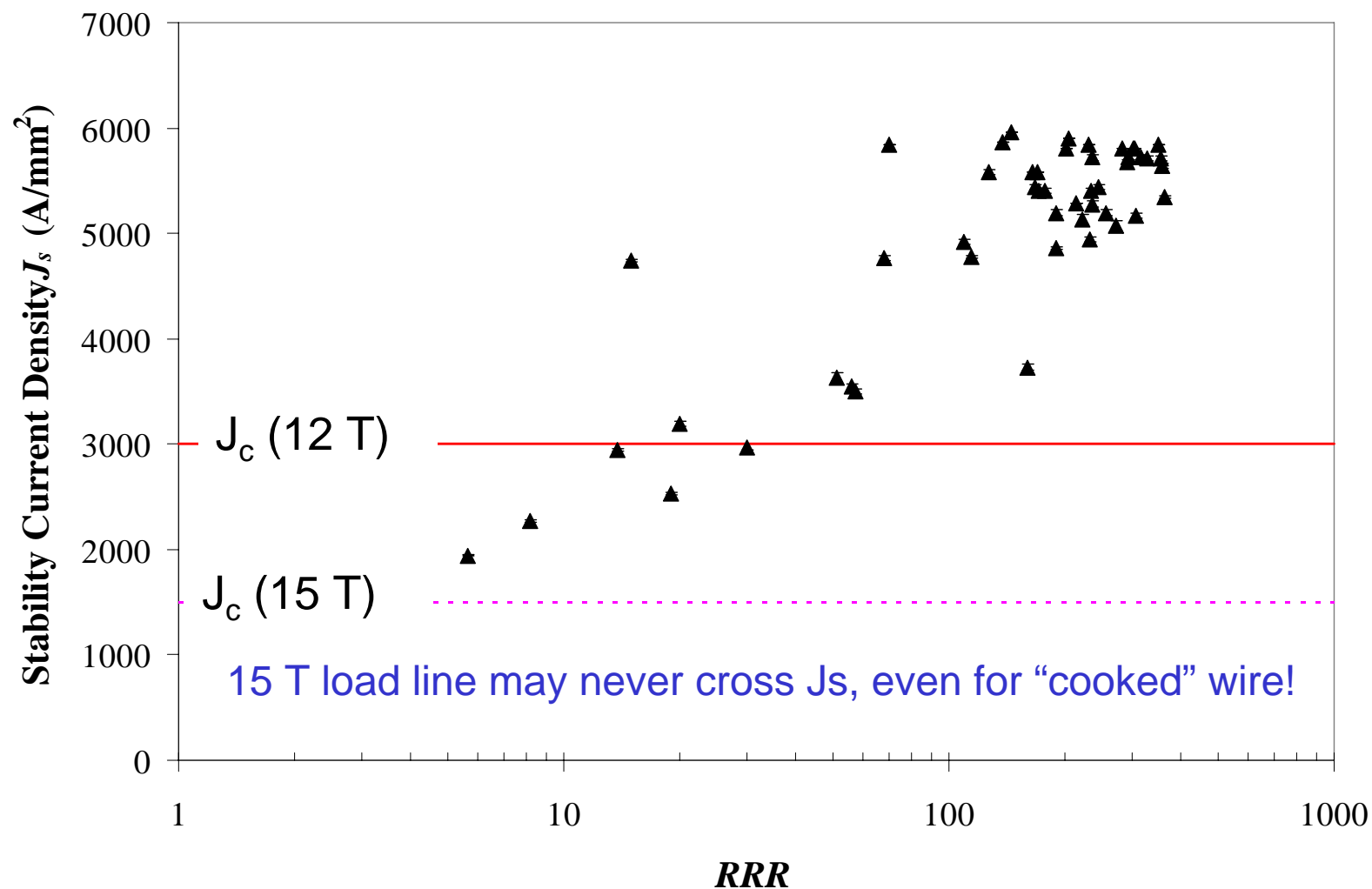
J_c (12T) BNL and OST 48-50h data



RRR as a function of reaction time and temperature



Stability current density of RRP 54/61 wire



Outline

- Factors that limit performance of superconductors
- Nb₃Sn: Why has RRP* has emerged over bronze-route, MJR†, and PIT‡ as the LARP strand process?
 - Maximizing current density
 - Overcoming limitations imposed by gradients of the tin content
 - Managing stability
- Is further improvement of Nb₃Sn possible?
- If not, what's next? Clues from emerging areas in superconducting materials for HEP

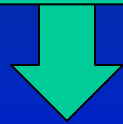
* Restacked Rod Process™

† Modified jelly-roll process

‡ Powder-in-tube process

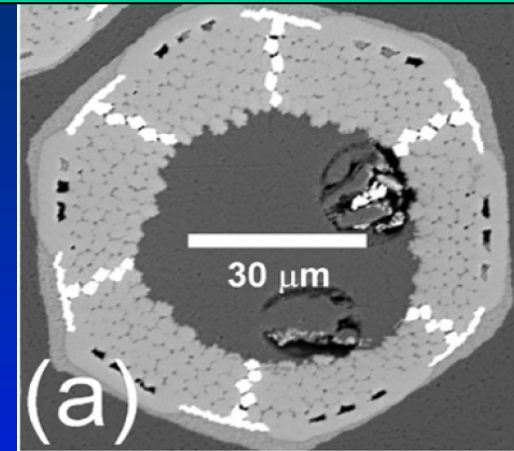
Toward smaller d_{eff}

Restacked Rod Process (RRP)
Subelements are not divided,
just smaller in diameter

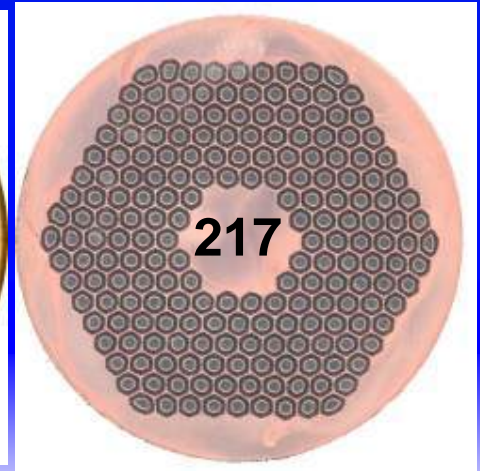
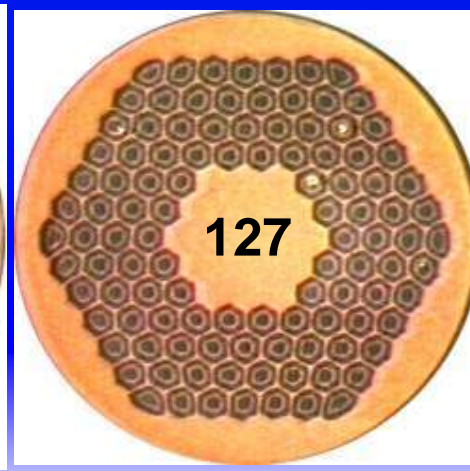
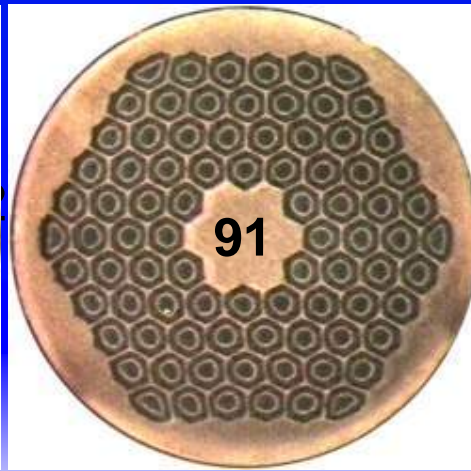
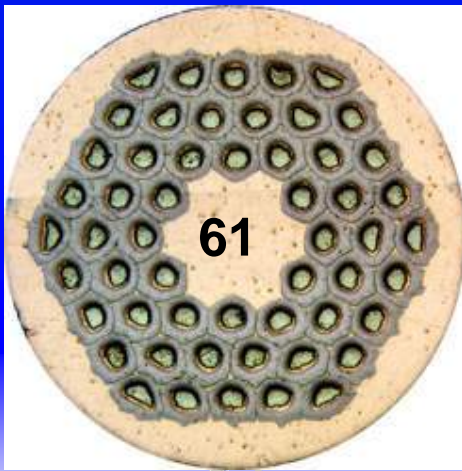


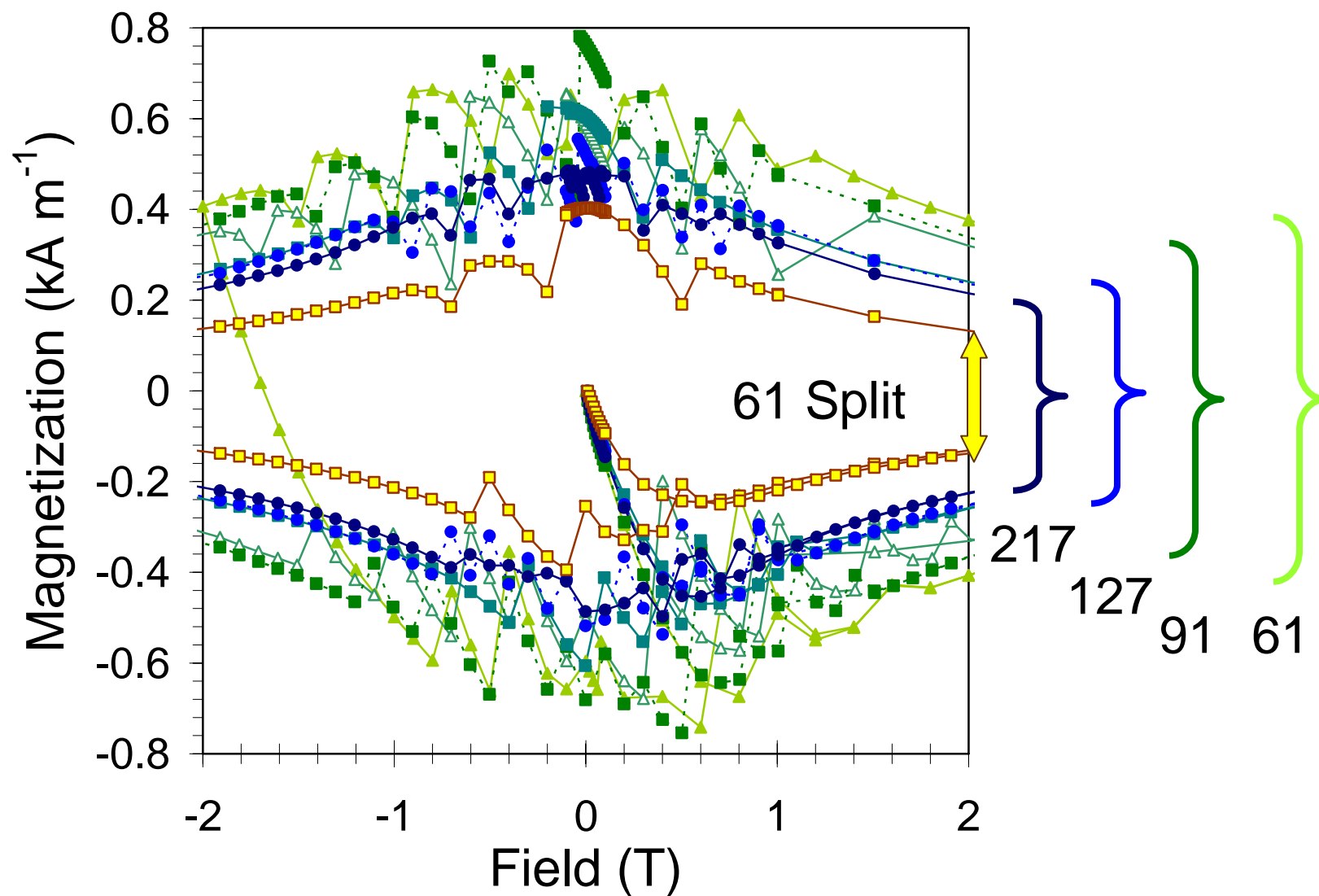
0.7 mm dia.

Also one composite with a
divided subelement

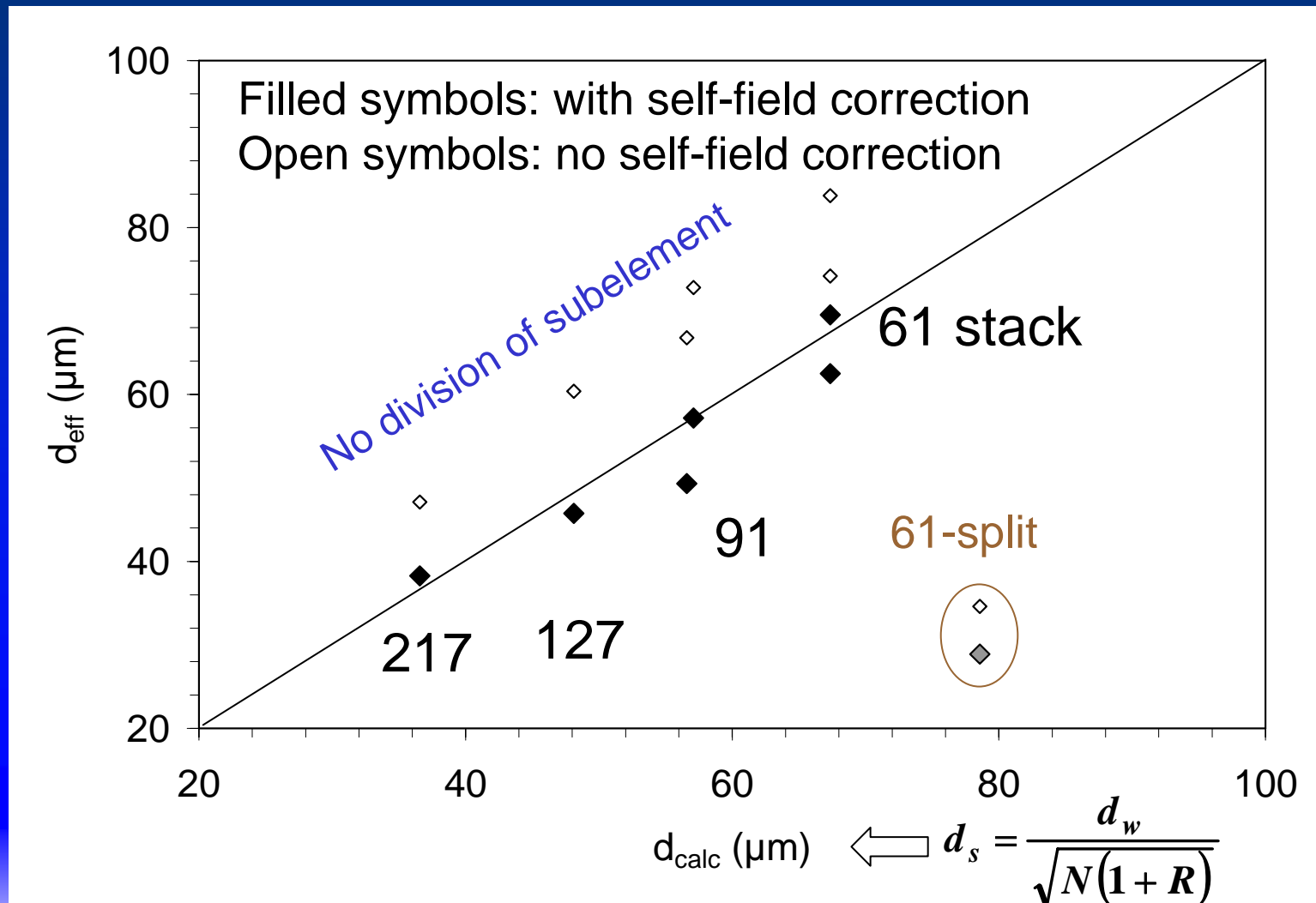


Courtesy Jeff Parrell ASC 2006





Effective filament diameter and subelement diameter are equal; 40 μm has been achieved!



Smaller d_{eff} comes with performance sacrifice

N	d_s μm	HT type	HT	$J_c(12)$ A mm^{-2}	RRR
54 (61)	68	A	72h@675°C	2900	6
		B	36@660	2985	47
		C	24@650	2760	127
84 (91)	57	B	48@650	3050	165
90 (91)	57	A	48@695	2680	20
		C	36@635	2330	344
108 (127)	49	B	48@665	2830	127
126 (127)	48	A	72@665	2260	4
		B	72@635	2040	9
		C	36@635	1910	114
198 (217)	37	B	48@650	2460	12
54 split	79	A	100@665	2290	6
		B	50@665	2120	96

Where to look for more layer Jc

- Grain size as small as 30 to 50 nm have been achieved (proof of principle)
- 50% gain in pinning might be realized by reducing grain size to ~80 nm
 - ~150 nm obtained for 650 to 665 °C right now
- **IN PROGRESS:** LARP 54/61
 - 2 x HT 96 h @ 620 °C
 - HT 150 h @ 605 °C

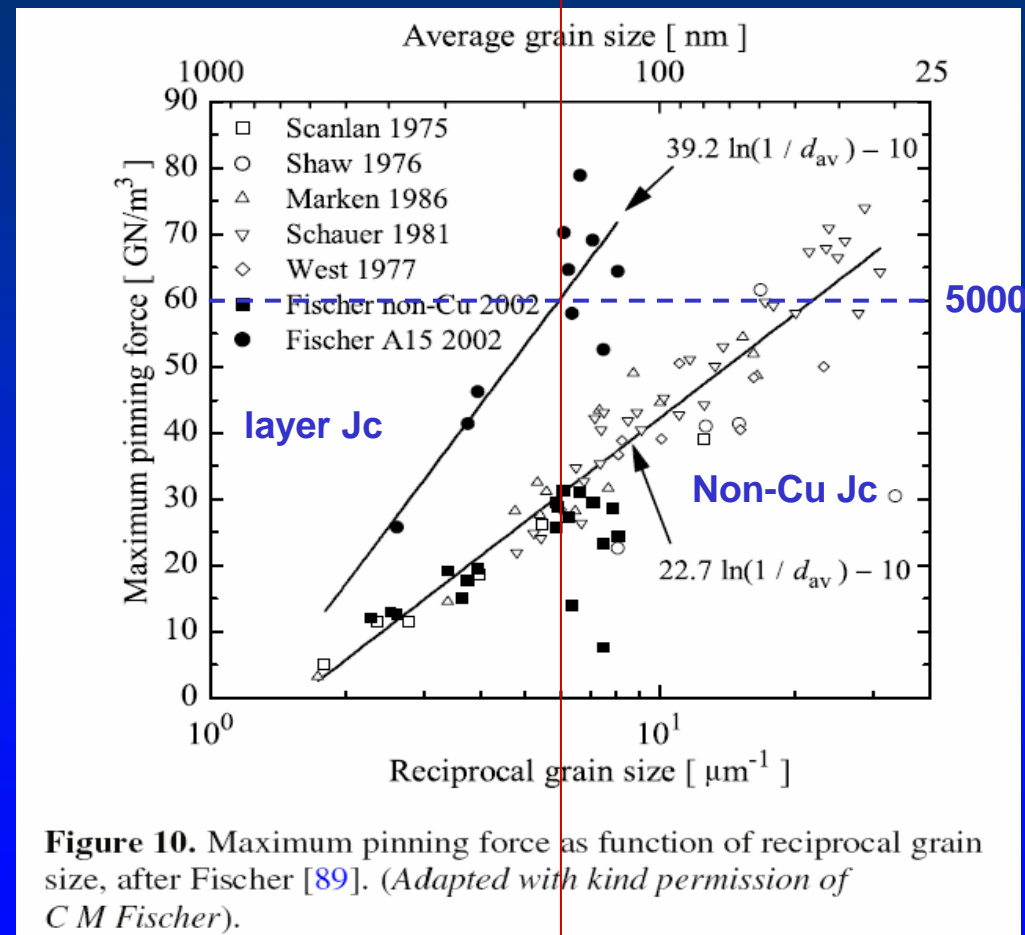


Figure 10. Maximum pinning force as function of reciprocal grain size, after Fischer [89]. (Adapted with kind permission of C M Fischer).

Can this line be moved to the right,
e.g. by a long reaction at 550 to 600 °C?

Can a wire design yield still higher Nb₃Sn %?

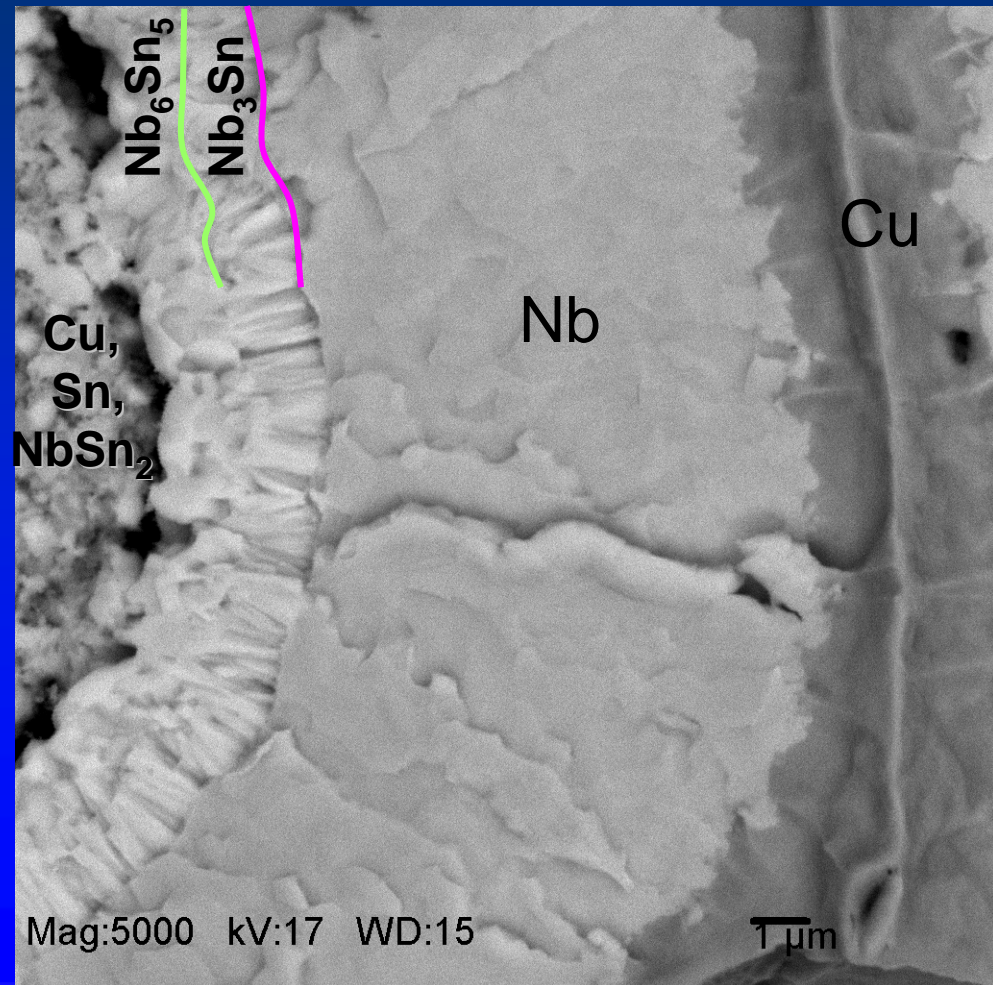
- Ultimate limit: 2 volume units Nb fully react with 1 unit Sn to provide 2.67 units Nb₃Sn
 - i.e., not more than 89% of non-copper area can be converted to Nb₃Sn when starting from elements
 - (2:1 volume = 3:1 mol Nb:Sn)
- Must let tin escape from core, else large grains form
 - PIT, RIT cannot therefore achieve the ultimate limit above!
- Lower LAR: increases Nb content, but pinches off tin diffusion
- Smaller Nb filaments at same LAR provides more access for Sn, but sacrifice shape control
- Better roundness of Nb and smaller Nb grain size will improve geometry stability, but this requires changes in Nb supply
- **ACTIVITIES IN PROGRESS UNDER CONDUCTOR DEVELOPMENT GROUP (OI-ST)**

Regarding trapped tin in PIT...

SMI billet 34
24 h @ 575°C

Lesson: It was not possible to form Nb_3Sn without first forming Nb_6Sn_5 , no matter how low the reaction temp.

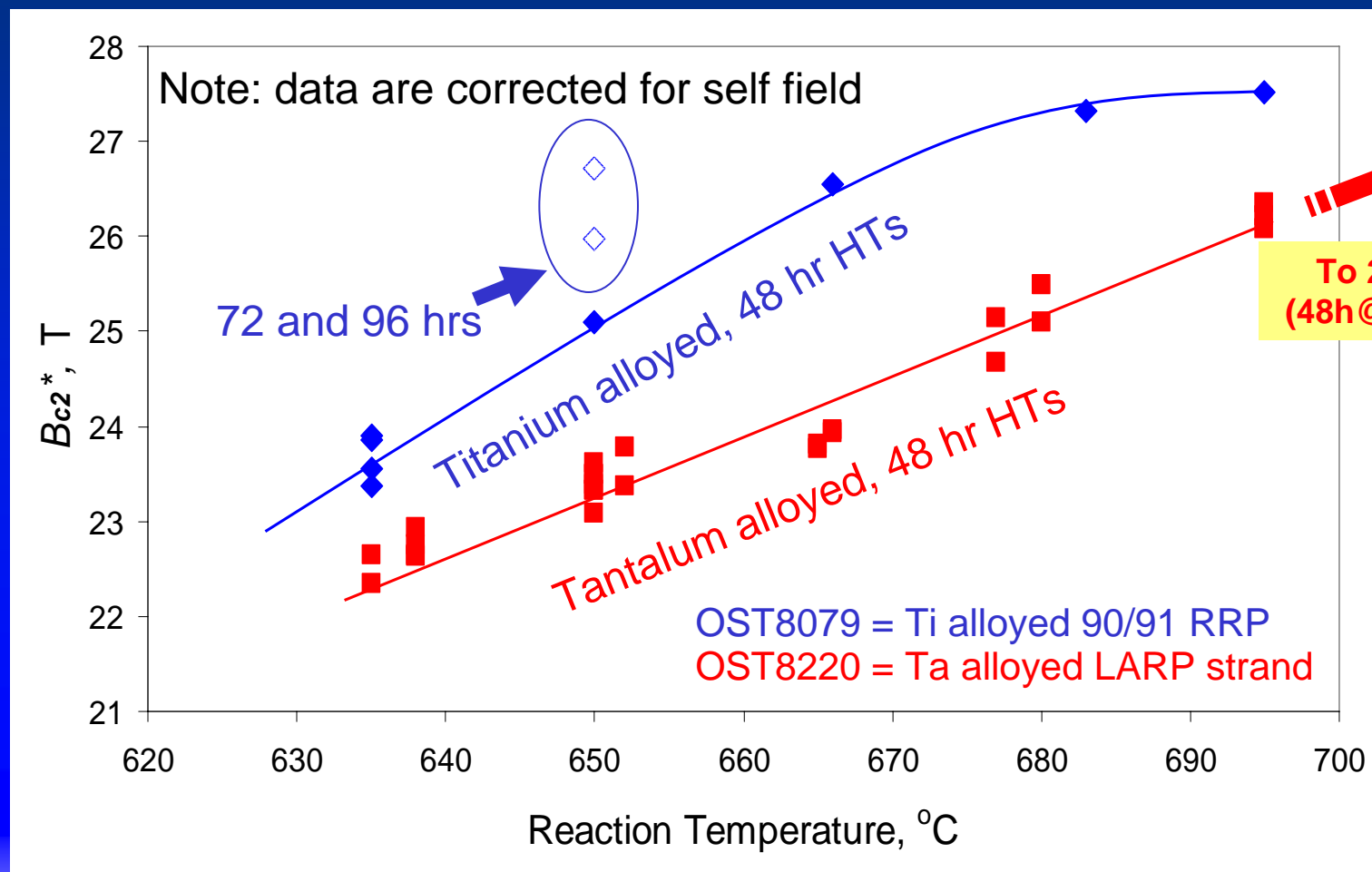
Can a thick layer of fine-grained Nb_6Sn_5 be formed first, and then converted to Nb_3Sn without coarsening?
(We were not successful)



SEM and prep by Jesse Wright & Bob Sabatini
Wire samples from FNAL

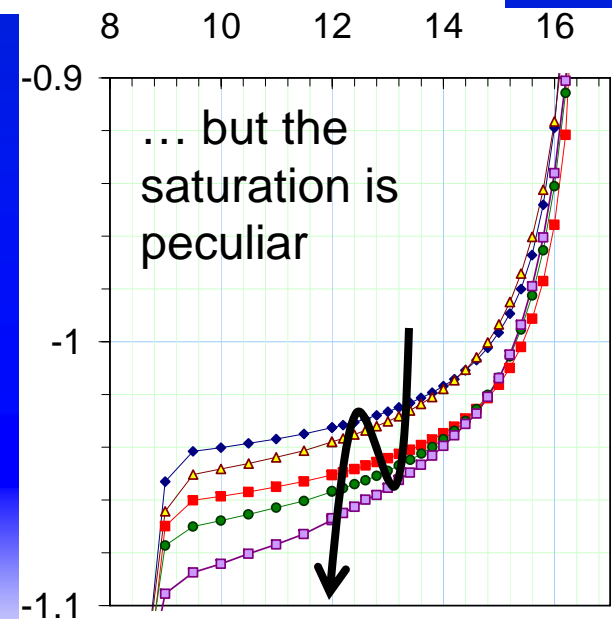
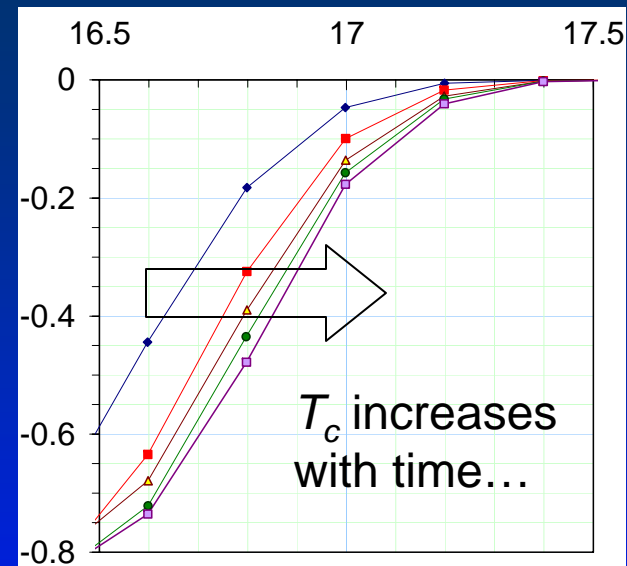
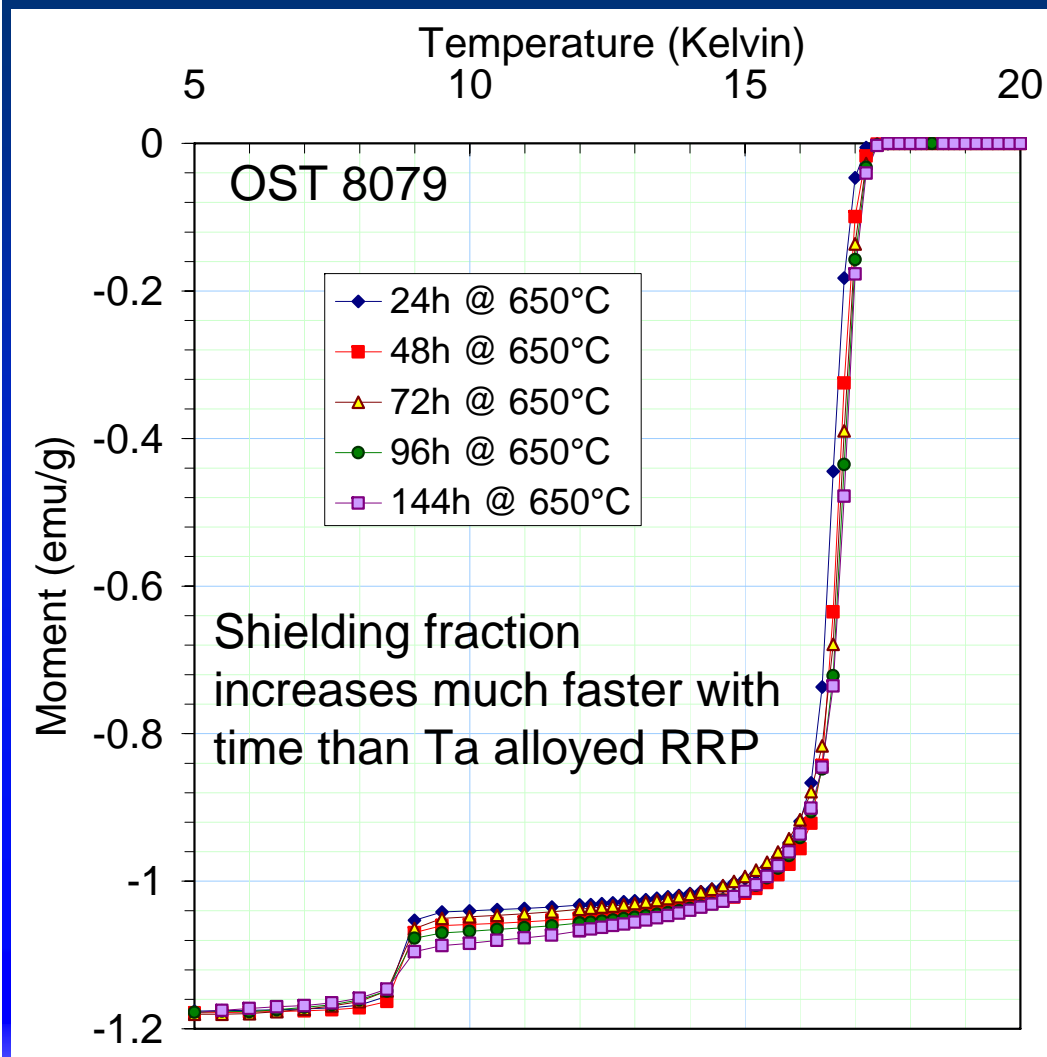
Ti alloying - Faster way to get high-field performance?

Kramer-plot extrapolated intercept

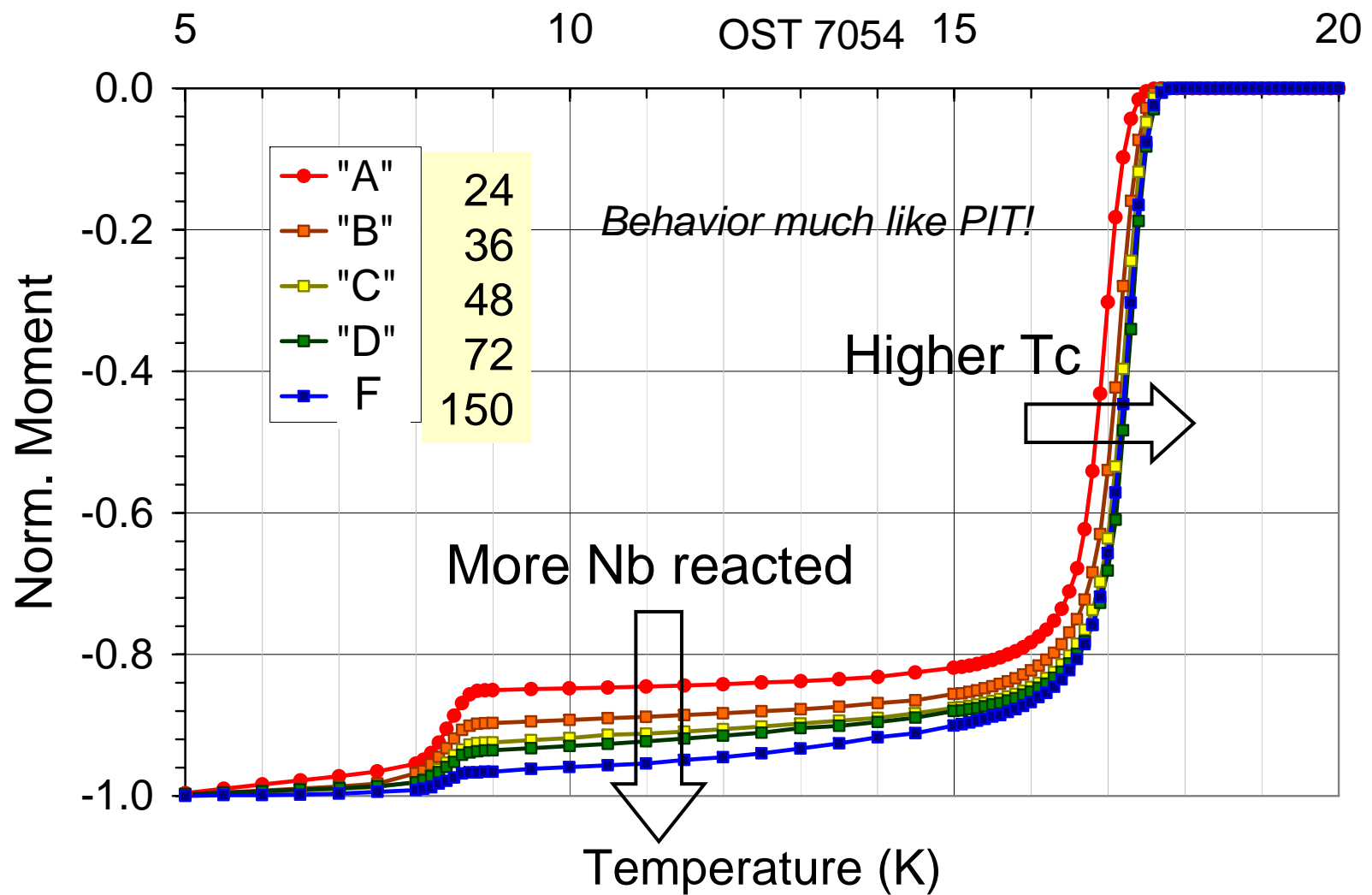


Ghosh, Cooley, OST collaborators ASC2006

Ti gradients as well as Sn gradients?



(Ta alloyed RRP for comparison)



What's going on with Ti?

- **Possibility 1:** Ti is a more effective alloying agent than Ta (contrary to past results...).
- Must adjust LAR to accommodate Ti diffusion
- **IN PROGRESS:** RRP 8079 given intermediate 575°C step to diffuse Ti uniformly prior to Nb₃Sn reaction
- **Possibility 2:** Better Ti results are an ARTIFACT of faster tin diffusion
 - It is known that Ti penetrates quickly along grain boundaries, which would widen the “pipes” through which tin flows.
- If so, then does Ti really alloy?
 - Past work: 2% Ti at GBs, 1.3% in Nb₃Sn region

Billet	Design %Ti	LAR	Max B_{c2}^*	Comment
RRP-8079	2.4	0.26	27.5	
HER-7981	2.5	0.28	26.5	Tin starved?
RRP-8720	2.0	0.20	25.8	B_{c2}^* decreases with HT time

Outline

- Factors that limit performance of superconductors
- Nb₃Sn: Why has RRP* has emerged over bronze-route, MJR†, and PIT‡ as the LARP strand process?
 - Maximizing current density
 - Overcoming limitations imposed by gradients of the tin content
 - Managing stability
- Is further improvement of Nb₃Sn possible?
- If not, what's next? Clues from emerging areas in superconducting materials for HEP

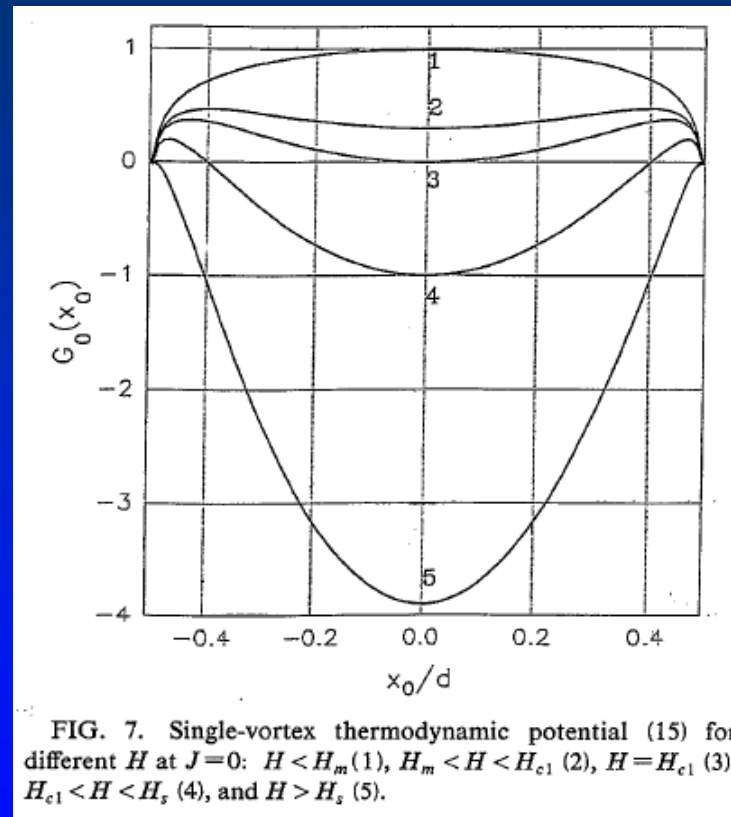
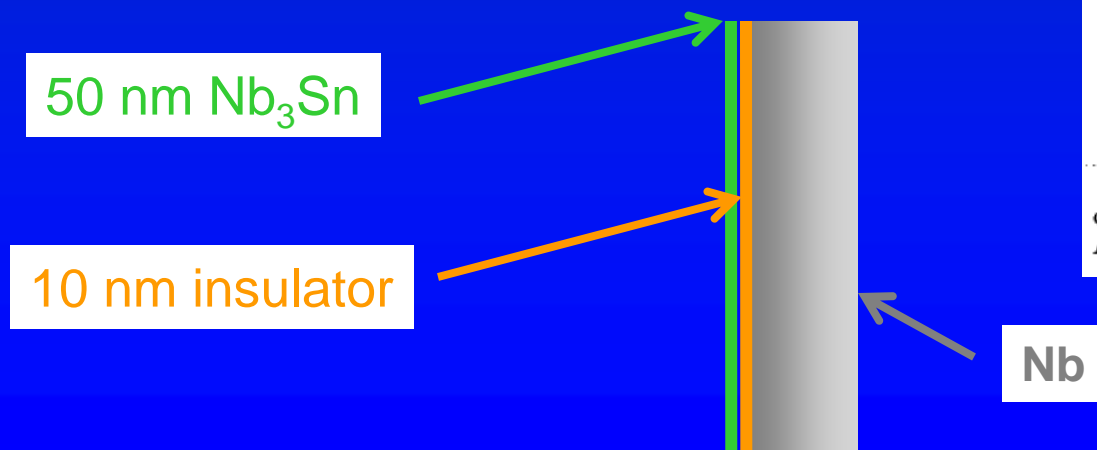
* Restacked Rod Process™

† Modified jelly-roll process

‡ Powder-in-tube process

SRF flux entry barrier: Breaking the Nb monopoly

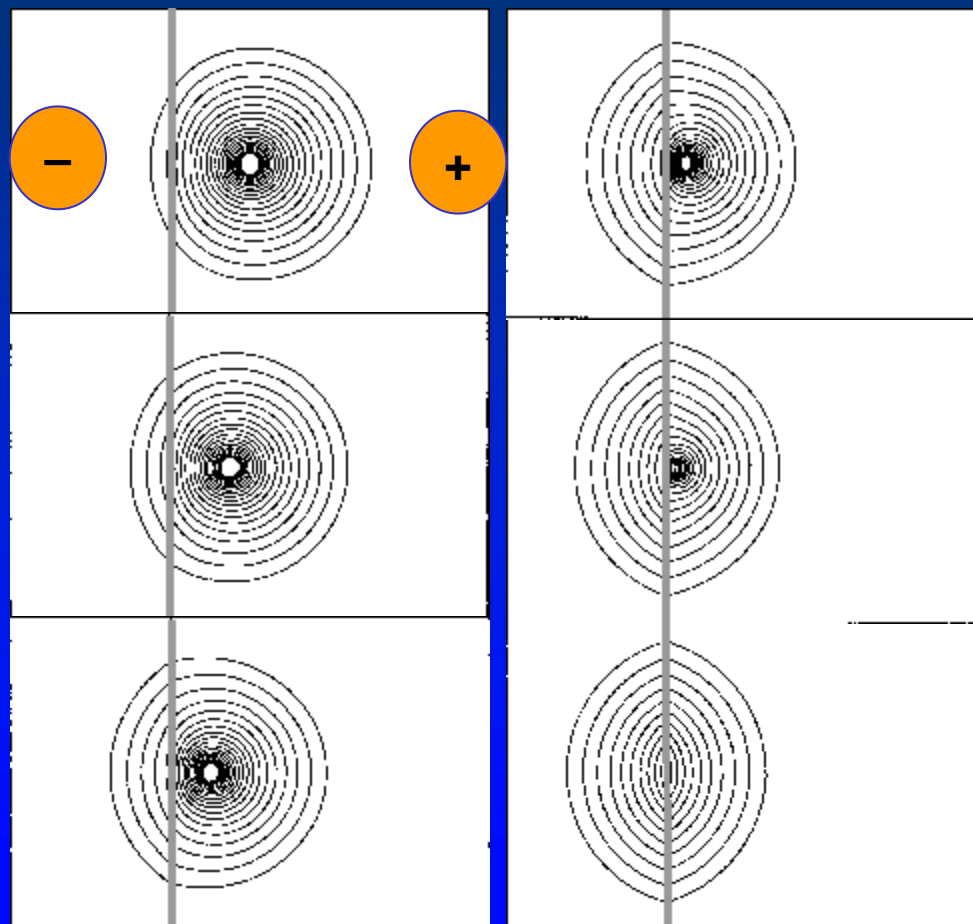
- A Gurevich: a thin layer of a high-field superconductor over Nb will keep out fluxons and their normal electrons
- $H_S \sim (\lambda_L / d) H_S^{\text{bulk}}$
- Several materials challenges!



$$H_s = \phi_0 / 2\pi d \xi .$$

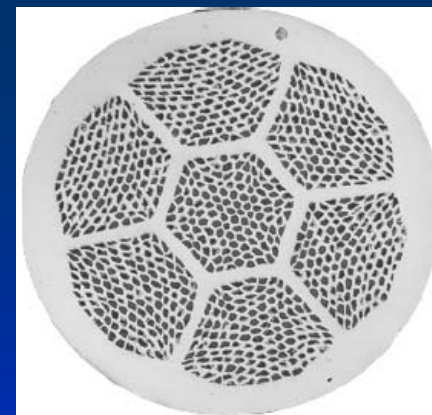
AJ vortices at Nb grain boundaries?

- “Hybrid” Abrikosov-Josephson vortices will penetrate boundaries even though the boundaries themselves do not obstruct current



50 T solenoid for muon cooling

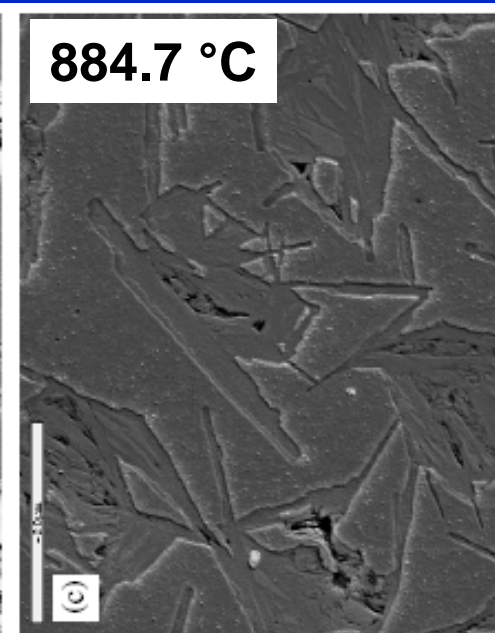
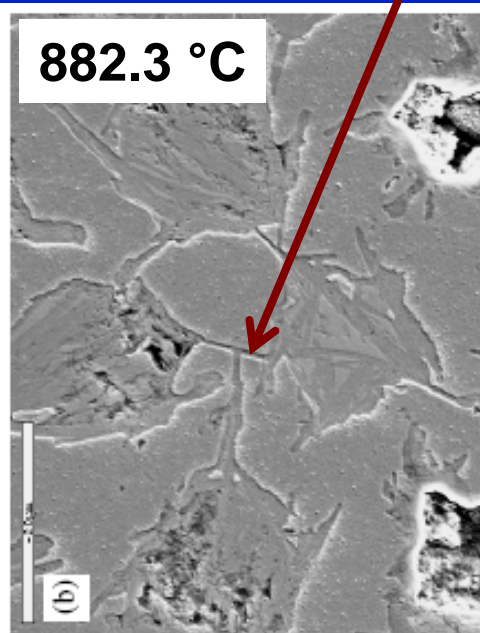
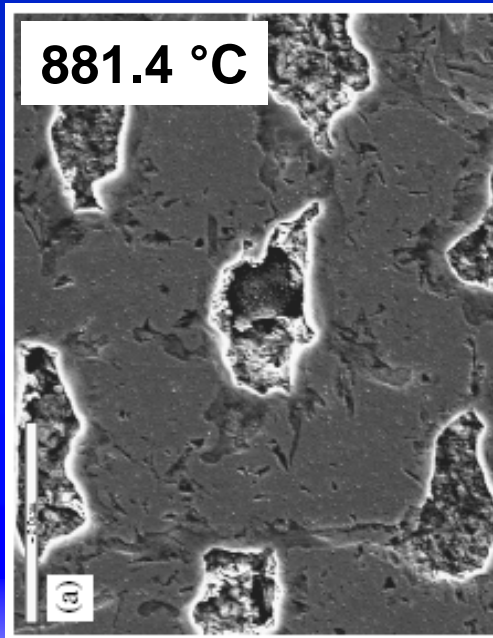
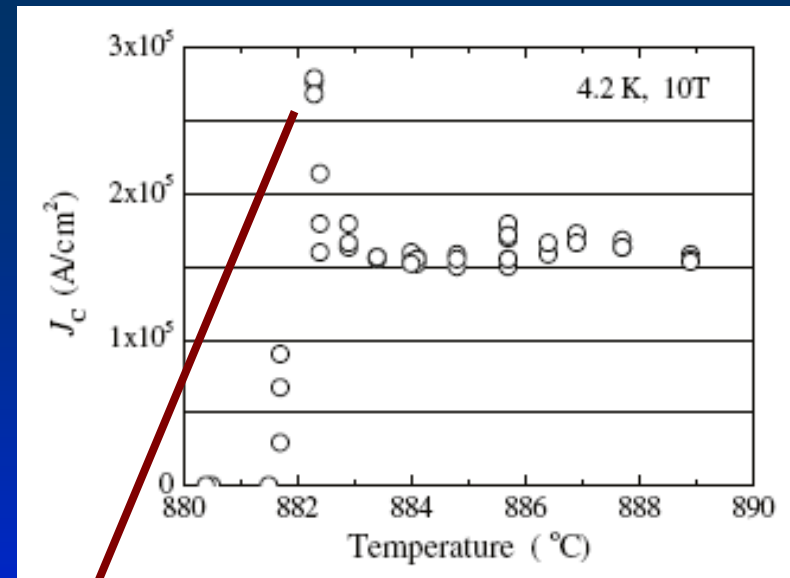
- A Bi-2212 + stainless steel monster?



Challenges

- Open the reaction window to enable wind and react
 - Reaction temperature depends on melting point of $\text{Bi}_{2+x}\text{Sr}_{2+y}\text{CaCu}_2\text{O}_8$ ceramic, which is sensitive to Bi:Sr ratio and must be controlled to $\pm 2^\circ\text{C}$ at $> 880^\circ\text{C}$
 - $\pm 15^\circ\text{C}$ possible but at expense of homogeneity and therefore current density (i.e. highest current density for smallest window)
 - How to heat a coil so uniformly?
- Explore react and wind
- Increase the current density and fill factor

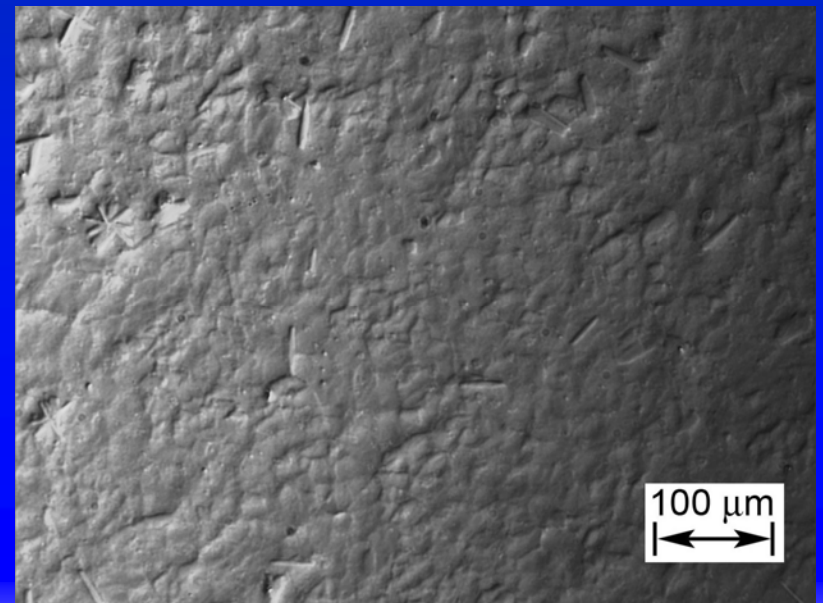
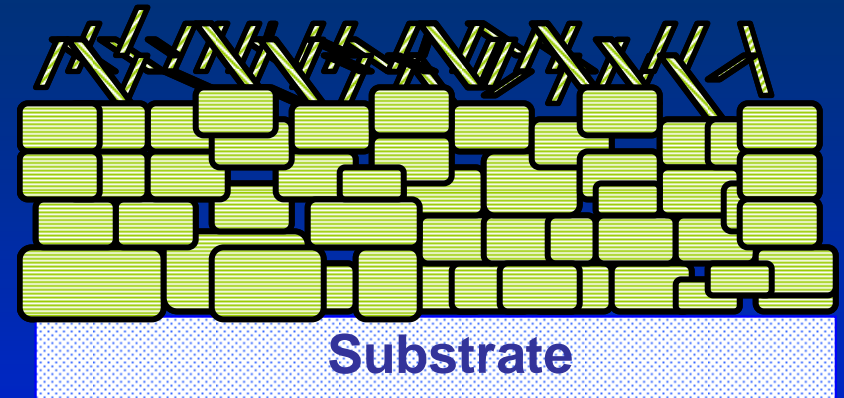
Thin needles carry most of the current!



Can magnet designers use tapes?

Horizon: thick YBCO in long length
1000 A/cm tape @ 77K, 0.1T
(= 2,500 A/cm @ >20T, 4.2K)

- Right now, basic research is making 100% gains in improving flux pinning
- Growth mechanisms are also better understood – new pathways toward thicker YBCO layers
 - Rapid nucleation provides grain-boundary-like pinning for the first time!



V. Solovyov et al, BNL

Summary

- RRP strand is the engineering material that will allow LARP magnet construction!
- Lesson: Vertical nature of discussions within DOE-AARP greatly accelerated development to suit needs of LARP.
 - HEP Low Temperature Superconductor Workshop: End users, industry, and materials scientists together in one room for 2.5 days on an annual basis!
 - Efforts continue under Conductor Development Program
- Can we do better to facilitate R&D?
 - Example: DOE / NSF Center of Excellence

Summary, cont.

- LARP strand has room for further improvement. Incremental advances are likely given present effort.
 - Must sustain for long term
 - Must allow curiosity to produce breakthroughs
- Changing specs often has repercussions!
 - Example: Nb grain size affects roundness and shape stability, which affect efficiency of tin diffusion and thereby J_c
- New materials offer new opportunities and present new challenges. We need to attack the scientific and technological questions with the same coherent vertical effort.

Acknowledgments

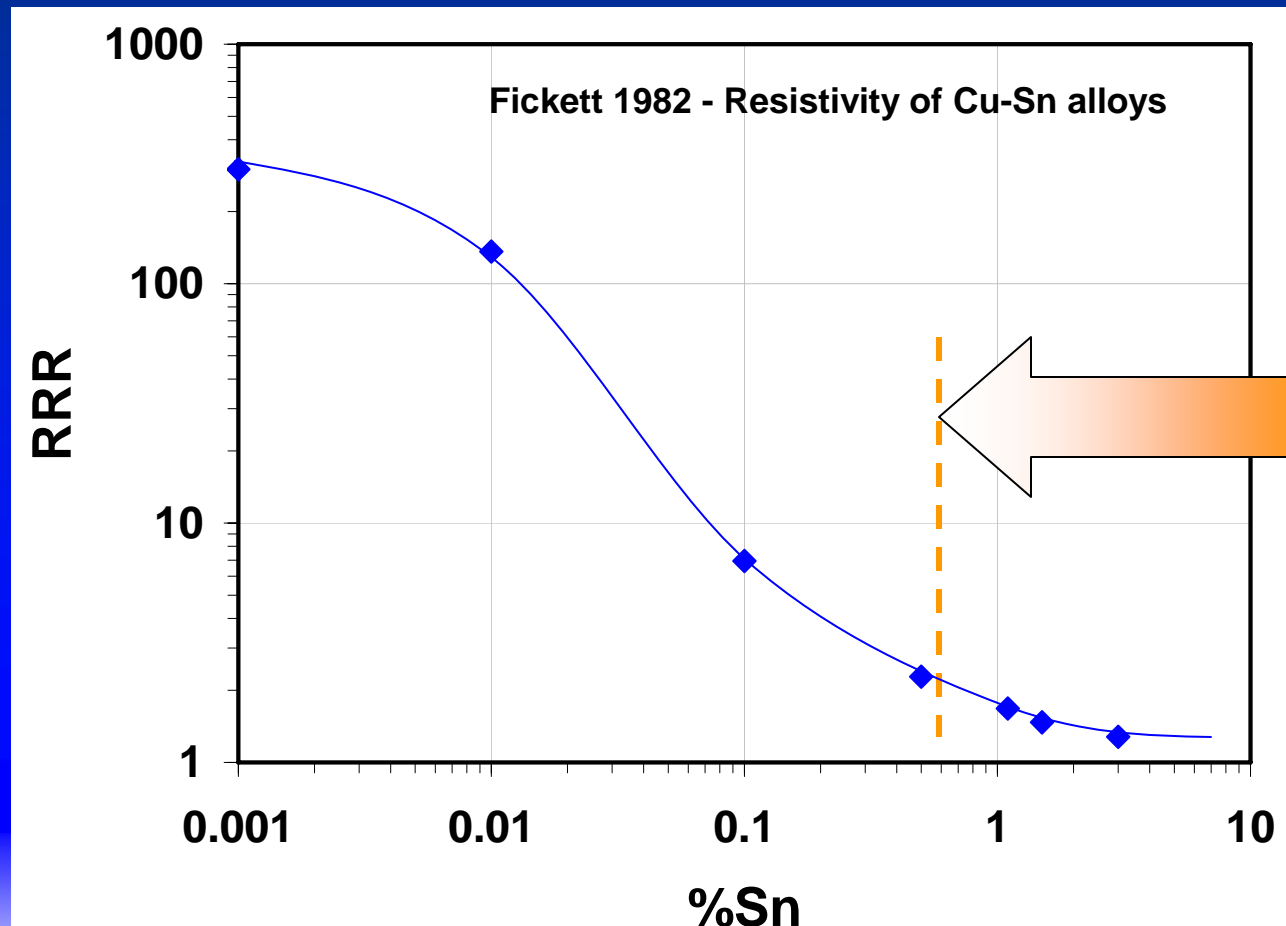
- **BNL Superconducting Magnet Division:** Arup Ghosh (co-PI), Ed Sperry, Joe D'Ambra
- **BNL CMPMSD:** Mas Suenaga, Arnold Moodenbaugh, Bob Sabatini, Jesse Wright (student), Paul Chang (student)
- **Wisconsin / NHMFL:** David Larbalestier, Peter Lee, Arno Godeke (now LBNL), Matt Jewell, Seth Hynes, Chad Fischer (now Intel), Chris Hawes (now Micron Semiconductor)
- **Oxford Instruments-Superconducting Technology:** Jeff Parrell, Mike Field, Seung Hong, Ken Marken (now LANL)

... And many pleasant discussions with the AARP community!

Reserve slides

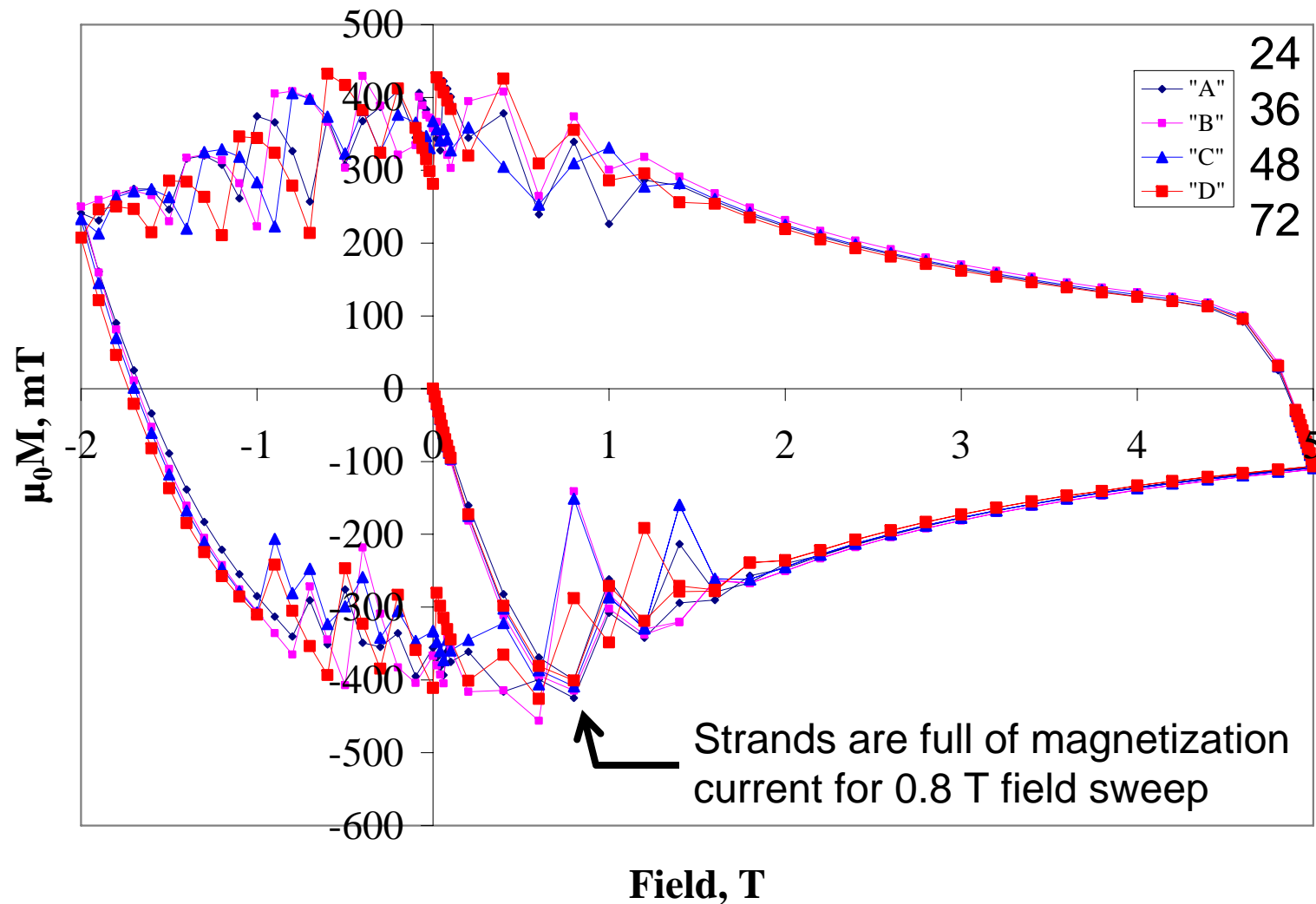
Tin destroys thermal conductivity of copper

- Tin is a potent electron scatterer: 0.1% Sn will reduce RRR from 300 to 7 —Fickett, Cryogenics vol. 22, p. 135 (1982)



Resolution limit of
Scanning Electron
Microscopy with
Energy-Dispersive
X-Ray
Spectroscopy
(SEM-EDX)

All reactions produce unstable strands because barrier reacts to form ring of Nb_3Sn around subelement



How contaminated is the copper?

SEM-EDX microanalyses:

- 120-300 sec., 17 kV
- 2,500-10,000 counts
- no Nb detected

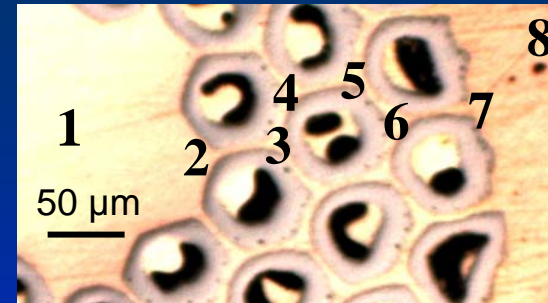


Table II. Atomic fraction of tin (%) determined by EDX as a function of location in Fig. 1 for various samples.

Location	Samples				
	A	C	D	E	F
1	<0.5	<0.5	<0.5	<0.5	0.66
2	<0.5	2.67	1.61	1.32	1.62
3	<0.5	4.26	2.69	3.02	1.72
4	<0.5	2.82	1.55	2.44	2.07
5	<0.5	2.41	1.52	2.17	1.88
6	<0.5	1.73	1.68	1.67	1.61
7	<0.5	0.60	0.59	0.51	0.64
8	<0.5	<0.5	<0.5	<0.5	<0.5

THERMAL PATHWAY
IS DEAD

Traditional V-I curve

